# SNx4LVC373A Octal Transparent D-Type Latches With 3-State Outputs

## 1 Features

- Operate From 1.65 V to 3.6 V
- Inputs Accept Voltages to 5.5 V
- Max $t_{pd}$ of 6.8 ns at 3.3 V
- Typical $V_{OLP}$ (Output Ground Bounce) <0.8 V at $V_{CC}$ = 3.3 V, $T_A$ = 25°C
- Typical $V_{OHV}$ (Output $V_{OH}$ Undershoot) >2 V at $V_{CC}$ = 3.3 V, $T_A$ = 25°C
- Supports Mixed-Mode Signal Operation on All Ports (5-V Input/Output Voltage With 3.3-V $V_{CC}$)
- $I_{off}$ Supports Live-Insertion, Partial-Power-Down Mode, and Back-Drive Protection
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)
- On Products Compliant to MIL-PRF-38535, All Parameters Are Tested Unless Otherwise Noted. On All Other Products, Production Processing Does Not Necessarily Include Testing of All Parameters.

## 2 Applications

- Network Switches
- TV Set-top Boxes
- Motor Drives
- PCs and Notebooks

## 3 Description

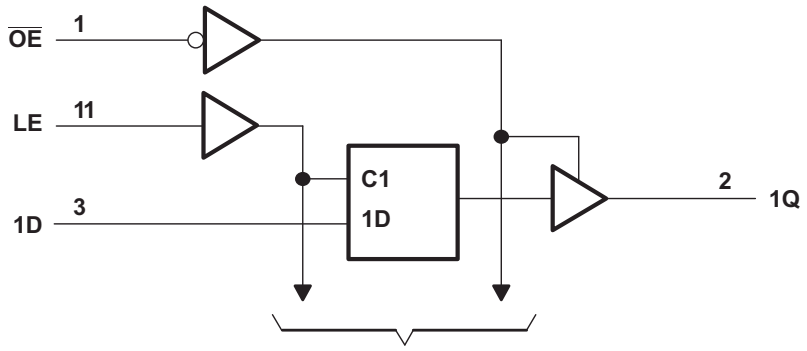
The SN54LVC373A octal transparent D-type latch is designed for 2.7-V to 3.6-V $V_{CC}$ operation, and the SN74LVC373A octal transparent D-type latch is designed for 1.65-V to 3.6-V $V_{CC}$ operation.

**Device Information(1)**

| PART NUMBER | PACKAGE | BODY SIZE (NOM) |
|---|---|---|
| SNx4LVC373A | SSOP (20) | 7.20 mm × 5.30 mm |
| | SOIC (20) | 12.80 mm × 7.50 mm |
| | PDIP (20) | 24.33 mm 6.35 mm |
| | TSSOP (20) | 6.50 mm × 4.40 mm |
| | VQFN (20) | 4.50 mm × 3.50 mm |

(1) For all available packages, see the orderable addendum at the end of the data sheet.

## 4 Simplified Schematic




Pin numbers shown are for the DB, DGV, DW, FK, J, N, NS, PW, RGY, and W packages.

An IMPORTANT NOTICE at the end of this data sheet addresses availability, warranty, changes, use in safety-critical applications, intellectual property matters and other important disclaimers. PRODUCTION DATA.

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## 5 Revision History

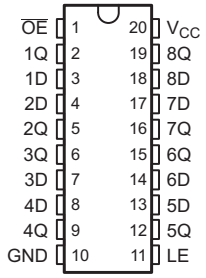
NOTE: Page numbers for previous revisions may differ from page numbers in the current version.

| Changes from Revision S (May 2005) to Revision T | Page |
|---|---|
| • Updated document to new TI data sheet format. | 1 |
| • Removed Ordering Information table. | 1 |
| • Changed $I_{off}$ Feature. | 1 |
| • Added Military Disclaimer to Features. | 1 |
| • Added Applications. | 1 |
| • Added Handling Ratings table. | 4 |
| • Changed MAX ambient temperature from 85°C to 125°C. | 5 |
| • Added Thermal Information table. | 5 |
| • Added Typical Characteristics. | 7 |
| • Added Detailed Description section | 9 |

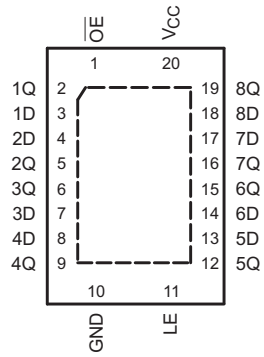

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# 6 Pin Configuration and Functions

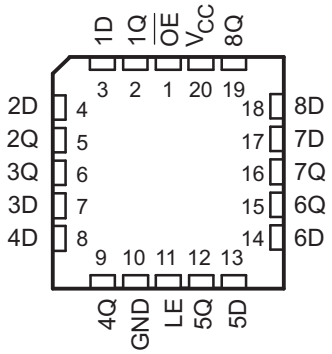
SN54LVC373A . . . J OR W PACKAGE
SN74LVC373A . . . DB, DGV, DW, N, NS, OR PW PACKAGE
(TOP VIEW)




SN74LVC373A . . . RGY PACKAGE
(TOP VIEW)




SN54LVC373A . . . FK PACKAGE
(TOP VIEW)




## Pin Functions

| PIN | | I/O | DESCRIPTION |
|---|---|---|---|
| NO. | NAME | | |
| 1 | $\overline{OE}$ | I | Enable Pin |
| 2 | 1Q | O | Output 1 |
| 3 | 1D | I | Input 1 |
| 4 | 2D | I | Input 2 |
| 5 | 2Q | O | Output 2 |
| 6 | 3Q | O | Output 3 |
| 7 | 3D | I | Input 3 |
| 8 | 4D | I | Input 4 |
| 9 | 4Q | O | Output 4 |
| 10 | GND | – | Ground Pin |
| 11 | LE | I | Latch Enable |
| 12 | 5Q | O | Output 5 |
| 13 | 5D | I | Input 5 |
| 14 | 6D | I | Input 6 |
| 15 | 6Q | O | Output 6 |
| 16 | 7Q | O | Output 7 |
| 17 | 7D | I | Input 7 |
| 18 | 8D | I | Input 8 |
| 19 | 8Q | O | Output 8 |
| 20 | VCC | – | Power Pin |

GQN OR ZQN PACKAGE
(TOP VIEW)

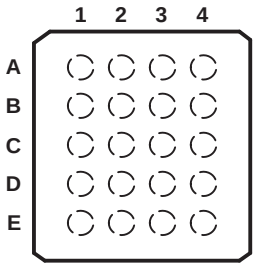



**Table 1. Pin Assignments**

| | 1 | 2 | 3 | 4 |
|---|---|---|---|---|
| **A** | 1Q | $\overline{OE}$ | $V_{CC}$ | 8Q |
| **B** | 2D | 7D | 1D | 8D |
| **C** | 3Q | 2Q | 6Q | 7Q |
| **D** | 4D | 5D | 3D | 6D |
| **E** | GND | 4Q | LE | 5Q |

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# 7 Specifications

## 7.1 Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

| | | | MIN | MAX | UNIT |
|---|---|---|---|---|---|
| $V_{CC}$ | Supply voltage range | | –0.5 | 6.5 | V |
| $V_I$ | Input voltage range(2) | | –0.5 | 6.5 | V |
| $V_O$ | Voltage range applied to any output in the high-impedance or power-off state(2) | | –0.5 | 6.5 | V |
| $V_O$ | Voltage range applied to any output in the high or low state(2)(3) | | –0.5 | $V_{CC}$ + 0.5 | V |
| $I_{IK}$ | Input clamp current | $V_I$ < 0 | | –50 | mA |
| $I_{OK}$ | Output clamp current | $V_O$ < 0 | | –50 | mA |
| $I_O$ | Continuous output current | | | ±50 | mA |
| | Continuous current through $V_{CC}$ or GND | | | ±100 | mA |

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
(2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
(3) The value of $V_{CC}$ is provided in the *Recommended Operating Conditions* table.

## 7.2 Handling Ratings

| | | | MIN | MAX | UNIT |
|---|---|---|---|---|---|
| $T_{stg}$ | Storage temperature range | | –65 | 150 | °C |
| $V_{(ESD)}$ | Electrostatic discharge | Human body model (HBM), per ANSI/ESDA/JEDEC JS-001, all pins(1) | 0 | 2000 | V |
| | | Charged device model (CDM), per JEDEC specification JESD22-C101, all pins(2) | 0 | 1000 | |

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.


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## 7.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)(1)

| | | | SN54LVC373A | | SN74LVC373A | | UNIT |
|---|---|---|---|---|---|---|---|
| | | | MIN | MAX | MIN | MAX | |
| $V_{CC}$ | Supply voltage | Operating | 2 | 3.6 | 1.65 | 3.6 | V |
| | | Data retention only | 1.5 | | 1.5 | | |
| $V_{IH}$ | High-level input voltage | $V_{CC}$ = 1.65 V to 1.95 V | | | 0.65 × $V_{CC}$ | | V |
| | | $V_{CC}$ = 2.3 V to 2.7 V | | | 1.7 | | |
| | | $V_{CC}$ = 2.7 V to 3.6 V | 2 | | 2 | | |
| $V_{IL}$ | Low-level input voltage | $V_{CC}$ = 1.65 V to 1.95 V | | | | 0.35 × $V_{CC}$ | V |
| | | $V_{CC}$ = 2.3 V to 2.7 V | | | | 0.7 | |
| | | $V_{CC}$ = 2.7 V to 3.6 V | | 0.8 | | 0.8 | |
| $V_I$ | Input voltage | | 0 | 5.5 | 0 | 5.5 | V |
| $V_O$ | Output voltage | High or low state | 0 | $V_{CC}$ | 0 | $V_{CC}$ | V |
| | | 3-state | 0 | 5.5 | 0 | 5.5 | |
| $I_{OH}$ | High-level output current | $V_{CC}$ = 1.65 V | | | | –4 | mA |
| | | $V_{CC}$ = 2.3 V | | | | –8 | |
| | | $V_{CC}$ = 2.7 V | | –12 | | –12 | |
| | | $V_{CC}$ = 3 V | | –24 | | –24 | |
| $I_{OL}$ | Low-level output current | $V_{CC}$ = 1.65 V | | | | 4 | mA |
| | | $V_{CC}$ = 2.3 V | | | | 8 | |
| | | $V_{CC}$ = 2.7 V | | 12 | | 12 | |
| | | $V_{CC}$ = 3 V | | 24 | | 24 | |
| Δt/Δv | Input transition rise or fall rate | | | 10 | | 10 | ns/V |
| $T_A$ | Operating free-air temperature | | –55 | 125 | –40 | 125 | °C |

(1) All unused inputs of the device must be held at $V_{CC}$ or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, (SCBA004).

## 7.4 Thermal Information

| THERMAL METRIC(1) | | SN74LVC373A | UNIT |
|---|---|---|---|
| | | PW | |
| | | 20 PINS | |
| $R_{\theta JA}$ | Junction-to-ambient thermal resistance | 102.5 | °C/W |
| $R_{\theta JC(top)}$ | Junction-to-case (top) thermal resistance | 35.9 | |
| $R_{\theta JB}$ | Junction-to-board thermal resistance | 53.5 | |
| $\psi_{JT}$ | Junction-to-top characterization parameter | 2.2 | |
| $\psi_{JB}$ | Junction-to-board characterization parameter | 52.9 | |
| $R_{\theta JC(bot)}$ | Junction-to-case (bottom) thermal resistance | n/a | |

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, SPRA953.

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## 7.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | | $V_{CC}$ | SN54LVC373A | | | SN74LVC373A | | | UNIT |
|---|---|---|---|---|---|---|---|---|---|---|
| | | | | MIN | TYP(1) | MAX | MIN | TYP(1) | MAX | |
| $V_{OH}$ | $I_{OH}$ = –100 µA | | 1.65 V to 3.6 V | | | | $V_{CC}$ – 0.2 | | | V |
| | | | 2.7 V to 3.6 V | $V_{CC}$ – 0.2 | | | | | | |
| | $I_{OH}$ = –4 mA | | 1.65 V | | | | 1.2 | | | |
| | $I_{OH}$ = –8 mA | | 2.3 V | | | | 1.7 | | | |
| | $I_{OH}$ = –12 mA | | 2.7 V | 2.2 | | | 2.2 | | | |
| | | | 3 V | 2.4 | | | 2.4 | | | |
| | $I_{OH}$ = –24 mA | | 3 V | 2.2 | | | 2.2 | | | |
| $V_{OL}$ | $I_{OL}$ = 100 µA | | 1.65 V to 3.6 V | | | | | | 0.2 | V |
| | | | 2.7 V to 3.6 V | | | 0.2 | | | | |
| | $I_{OL}$ = 4 mA | | 1.65 V | | | | | | 0.45 | |
| | $I_{OL}$ = 8 mA | | 2.3 V | | | | | | 0.7 | |
| | $I_{OL}$ = 12 mA | | 2.7 V | | | 0.4 | | | 0.4 | |
| | $I_{OL}$ = 24 mA | | 3 V | | | 0.55 | | | 0.55 | |
| $I_I$ | $V_I$ = 0 to 5.5 V | | 3.6 V | | | ±5 | | | ±5 | µA |
| $I_{off}$ | $V_I$ or $V_O$ = 5.5 V | | 0 | | | | | | ±10 | µA |
| $I_{OZ}$ | $V_O$ = 0 to 5.5 V | | 3.6 V | | | ±15 | | | ±10 | µA |
| $I_{CC}$ | $V_I$ = $V_{CC}$ or GND | $I_O$ = 0 | 3.6 V | | | 10 | | | 10 | µA |
| | 3.6 V ≤ $V_I$ ≤ 5.5 V(2) | | | | | 10 | | | 10 | |
| $\Delta I_{CC}$ | One input at $V_{CC}$ – 0.6 V, Other inputs at $V_{CC}$ or GND | | 2.7 V to 3.6 V | | | 500 | | | 500 | µA |
| $C_i$ | $V_I$ = $V_{CC}$ or GND | | 3.3 V | | 4 | 12 | | 4 | | pF |
| $C_o$ | $V_O$ = $V_{CC}$ or GND | | 3.3 V | | 5.5 | 12 | | 5.5 | | pF |

(1) All typical values are at $V_{CC}$ = 3.3 V, $T_A$ = 25°C.
(2) This applies in the disabled state only.

## 7.6 Timing Requirements, SN54LVC373A

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 3)

| PARAMETER | | SN54LVC373A | | | | UNIT |
|---|---|---|---|---|---|---|
| | | $V_{CC}$ = 2.7 V | | $V_{CC}$ = 3.3 V ± 0.3 V | | |
| | | MIN | MAX | MIN | MAX | |
| $t_w$ | Pulse duration, LE high | 3.3 | | 3.3 | | ns |
| $t_{su}$ | Setup time, data before LE↓ | 2 | | 2 | | ns |
| $t_h$ | Hold time, data after LE↓ | 2 | | 2 | | ns |

## 7.7 Timing Requirements, SN74LVC373A

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 3)

| PARAMETER | | SN74LVC373A | | | | | | | | UNIT |
|---|---|---|---|---|---|---|---|---|---|---|
| | | $V_{CC}$ = 1.8 V ± 0.15 V | | $V_{CC}$ = 2.5 V ± 0.2 V | | $V_{CC}$ = 2.7 V | | $V_{CC}$ = 3.3 V ± 0.3 V | | |
| | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | |
| $t_w$ | Pulse duration, LE high | 9 | | 4 | | 3.3 | | 3.3 | | ns |
| $t_{su}$ | Setup time, data before LE↓ | 6 | | 4 | | 2 | | 2 | | ns |
| $t_h$ | Hold time, data after LE↓ | 4 | | 2 | | 1.5 | | 1.5 | | ns |


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## 7.8 Switching Characteristics, SN54LVC373A

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 3)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | SN54LVC373A | | | | UNIT |
|---|---|---|---|---|---|---|---|
| | | | $V_{CC}$ = 2.7 V | | $V_{CC}$ = 3.3 V ± 0.3 V | | |
| | | | MIN | MAX | MIN | MAX | |
| $t_{pd}$ | D | Q | | 8.5 | 1 | 7.5 | ns |
| | LE | | | 9.5 | 1 | 8.5 | |
| $t_{en}$ | $\overline{OE}$ | Q | | 8.7 | 1 | 7.7 | ns |
| $t_{dis}$ | $\overline{OE}$ | Q | | 8 | 0.5 | 7 | ns |

## 7.9 Switching Characteristics, SN74LVC373A

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 3)

| PARAMETER | FROM (INPUT) | TO (OUTPUT) | SN74LVC373A | | | | | | | | UNIT |
|---|---|---|---|---|---|---|---|---|---|---|---|
| | | | $V_{CC}$ = 1.8 V ± 0.15 V | | $V_{CC}$ = 2.5 V ± 0.2 V | | $V_{CC}$ = 2.7 V | | $V_{CC}$ = 3.3 V ± 0.3 V | | |
| | | | MIN | MAX | MIN | MAX | MIN | MAX | MIN | MAX | |
| $t_{pd}$ | D | Q | 1 | 19.1 | 1 | 9.6 | | 7.8 | 1.5 | 6.8 | ns |
| | LE | | 1 | 22.8 | 1 | 10.5 | | 8.2 | 2 | 7.6 | |
| $t_{en}$ | $\overline{OE}$ | Q | 1 | 20 | 1 | 10.5 | | 8.7 | 1.5 | 7.7 | ns |
| $t_{dis}$ | $\overline{OE}$ | Q | 1 | 19.3 | 1 | 7.8 | | 7.6 | 1.5 | 7 | ns |
| $t_{sk(o)}$ | | | | 1 | | 1 | | 1 | | 1 | ns |

## 7.10 Operating Characteristics

$T_A$ = 25°C

| PARAMETER | | | TEST CONDITIONS | $V_{CC}$ = 1.8 V | $V_{CC}$ = 2.5 V | $V_{CC}$ = 3.3 V | UNIT |
|---|---|---|---|---|---|---|---|
| | | | | TYP | TYP | TYP | |
| $C_{pd}$ | Power dissipation capacitance per latch | Outputs enabled | f = 10 MHz | 61 | 56 | 46 | pF |
| | | Outputs disabled | | 3 | 3 | 3 | |

## 7.11 Typical Characteristics

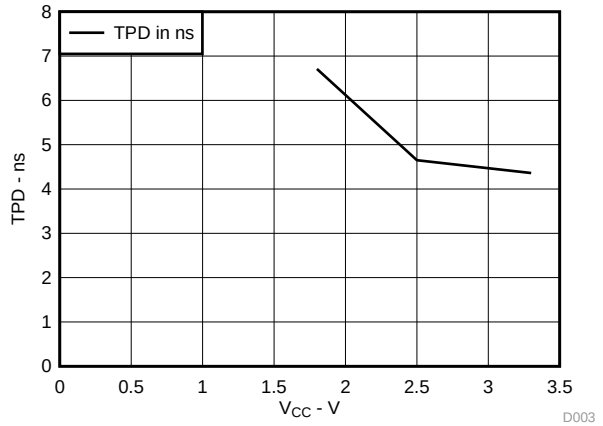



**Figure 1. SN74LVC373A LE to Q TDP $V_{CC}$ vs TPD at 25°C**

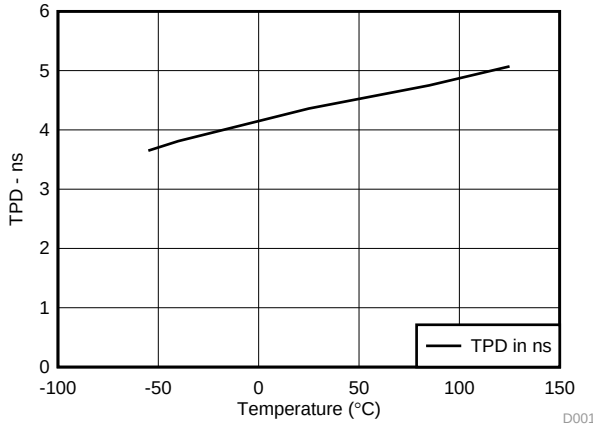
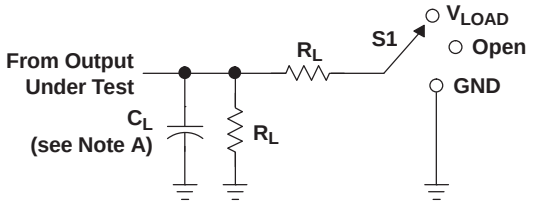



**Figure 2. SN74LVC373A LE to Q Across Temperature at 3.3-V $V_{CC}$**

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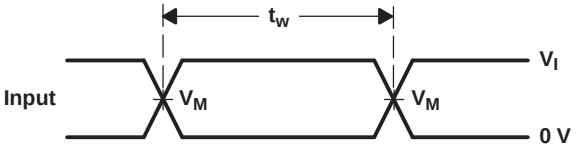
# 8 Parameter Measurement Information



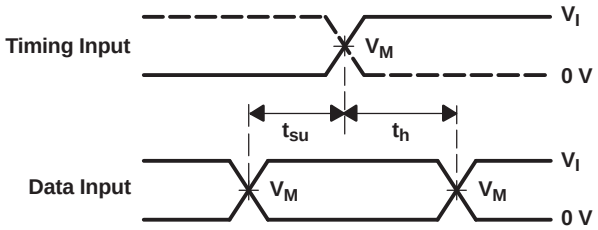

LOAD CIRCUIT

| TEST | S1 |
|---|---|
| $t_{PLH}/t_{PHL}$ | Open |
| $t_{PLZ}/t_{PZL}$ | $V_{LOAD}$ |
| $t_{PHZ}/t_{PZH}$ | GND |

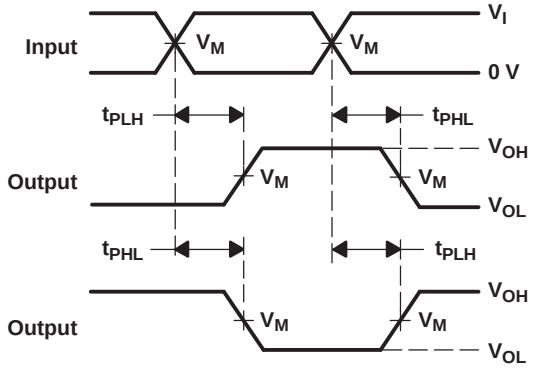
| $V_{CC}$ | INPUTS | | $V_M$ | $V_{LOAD}$ | $C_L$ | $R_L$ | $V_\Delta$ |
|---|---|---|---|---|---|---|---|
| | $V_I$ | $t_r/t_f$ | | | | | |
| 1.8 V ± 0.15 V | $V_{CC}$ | ≤2 ns | $V_{CC}/2$ | $2 \times V_{CC}$ | 30 pF | 1 kΩ | 0.15 V |
| 2.5 V ± 0.2 V | $V_{CC}$ | ≤2 ns | $V_{CC}/2$ | $2 \times V_{CC}$ | 30 pF | 500 Ω | 0.15 V |
| 2.7 V | 2.7 V | ≤2.5 ns | 1.5 V | 6 V | 50 pF | 500 Ω | 0.3 V |
| 3.3 V ± 0.3 V | 2.7 V | ≤2.5 ns | 1.5 V | 6 V | 50 pF | 500 Ω | 0.3 V |



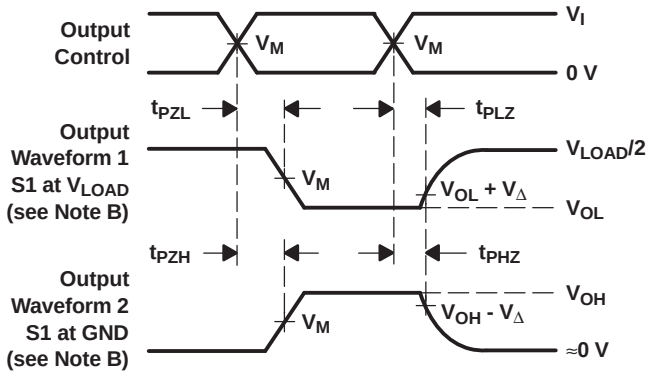

VOLTAGE WAVEFORMS
PULSE DURATION




VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES




VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS




VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

NOTES: A. $C_L$ includes probe and jig capacitance.
B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
C. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, $Z_O$ = 50 Ω.
D. The outputs are measured one at a time, with one transition per measurement.
E. $t_{PLZ}$ and $t_{PHZ}$ are the same as $t_{dis}$.
F. $t_{PZL}$ and $t_{PZH}$ are the same as $t_{en}$.
G. $t_{PLH}$ and $t_{PHL}$ are the same as $t_{pd}$.
H. All parameters and waveforms are not applicable to all devices.

**Figure 3. Load Circuit and Voltage Waveforms**


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# 9 Detailed Description

## 9.1 Overview

While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When LE is taken low, the Q outputs are latched at the logic levels set up at the D inputs.

A buffered output-enable ($\overline{OE}$) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without interface or pullup components.

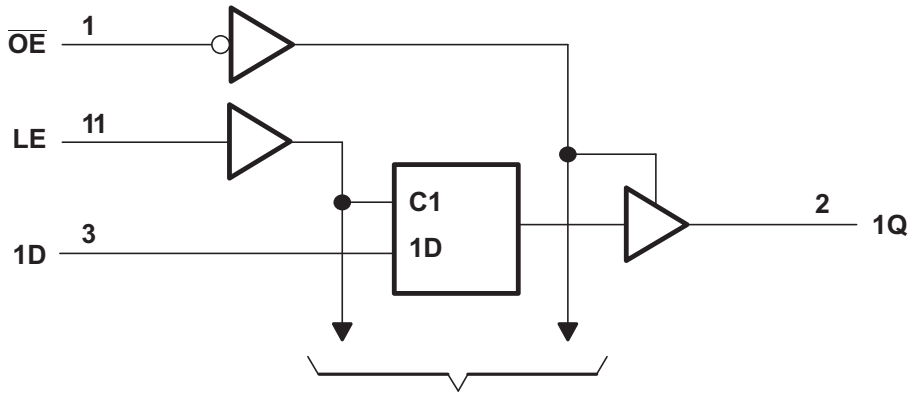
$\overline{OE}$ does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

These devices are fully specified for partial-power-down applications using $I_{off}$. The $I_{off}$ circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to $V_{CC}$ through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

## 9.2 Functional Block Diagram




Pin numbers shown are for the DB, DGV, DW, FK, J, N, NS, PW, RGY, and W packages.

## 9.3 Feature Description

- Wide operating voltage range
  - Operates from 1.65 V to 3.6 V
- Allows down voltage translation
  - Inputs accept voltages to 5.5 V
- $I_{off}$ feature
  - Allows voltages on the inputs and outputs when $V_{CC}$ is 0 V

## 9.4 Device Functional Modes

**Table 2. Function Table (Each Latch)**

| INPUTS | | | OUTPUT |
|---|---|---|---|
| $\overline{OE}$ | LE | D | Q |
| L | H | H | H |
| L | H | L | L |
| L | L | X | $Q_0$ |
| H | X | X | Z |


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# 10 Application and Implementation

## 10.1 Application Information

The SN74LVC373A is a high-drive CMOS device that can be used for a multitude of bus-interface type applications where the data needs to be retained or latched. It can produce 24 mA of drive current at 3.3 V. Therefore, this device is ideal for driving multiple outputs and for high speed applications up to 100 Mhz. The inputs are 5.5 V tolerant allowing it to translate down to $V_{CC}$.

## 10.2 Typical Application

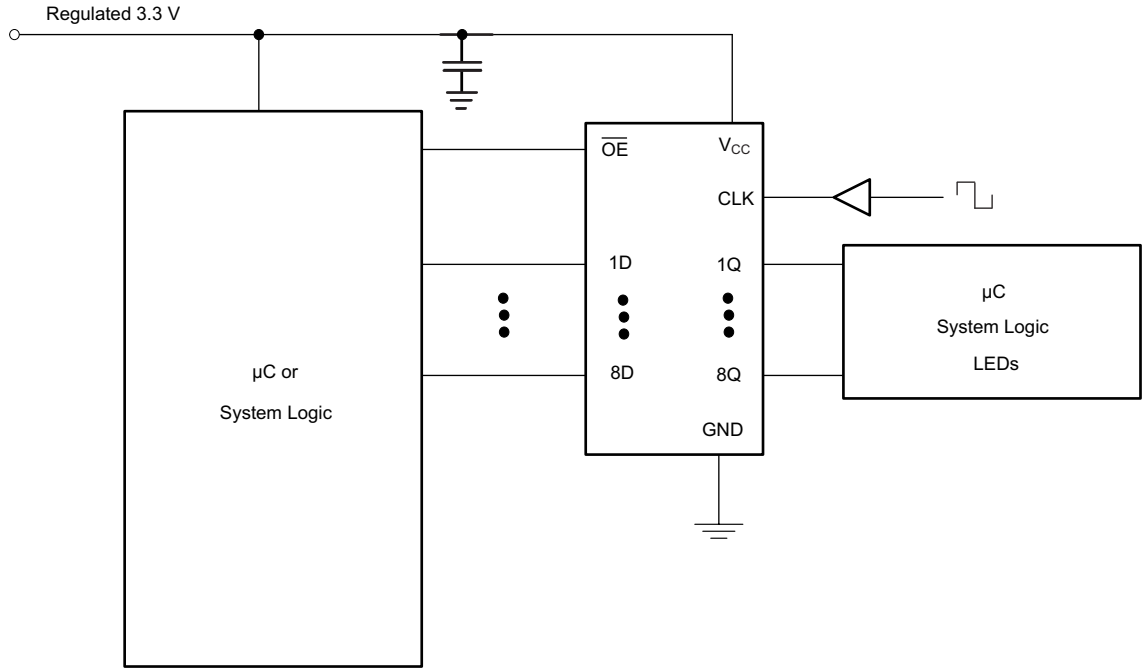



**Figure 4. Typical Application Diagram**

### 10.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Care should be taken to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads; therefore, routing and load conditions should be considered to prevent ringing.

### 10.2.2 Detailed Design Procedure

1. Recommended Input Conditions
   - Rise time and fall time specs: See (Δt/ΔV) in the *Recommended Operating Conditions* table.
   - Specified high and low levels: See ($V_{IH}$ and $V_{IL}$) in the *Recommended Operating Conditions* table.
   - Inputs are overvoltage tolerant allowing them to go as high as 5.5 V at any valid $V_{CC}$.
2. Recommend Output Conditions
   - Load currents should not exceed 50 mA per output and 100 mA total for the part.
   - Outputs should not be pulled above $V_{CC}$.

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## Typical Application (continued)

### 10.2.3 Application Curves

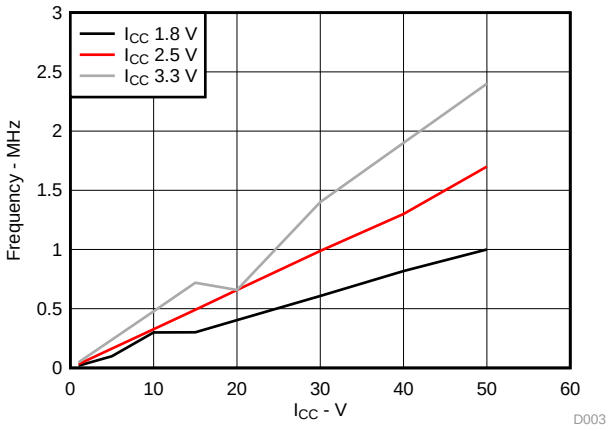



**Figure 5. $I_{CC}$ vs Frequency**

## 11 Power Supply Recommendations

The power supply can be any voltage between the MIN and MAX supply voltage rating located in the *Recommended Operating Conditions* table.

Each $V_{CC}$ pin should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, 0.1 µf is recommended; if there are multiple $V_{CC}$ pins, then 0.01 µf or 0.022 µf is recommended for each power pin. It is acceptable to parallel multiple bypass caps to reject different frequencies of noise. A 0.1 µf and a 1 µf are commonly used in parallel. The bypass capacitor should be installed as close to the power pin as possible for best results.

## 12 Layout

### 12.1 Layout Guidelines

When using multiple bit logic devices inputs should never float.

In many cases, functions or parts of functions of digital logic devices are unused, for example, when only two inputs of a triple-input AND gate are used or only 3 of the 4 buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. Figure 6 specifies the rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or $V_{CC}$, whichever makes more sense or is more convenient. It is generally acceptable to float outputs, unless the part is a transceiver.

### 12.2 Layout Example

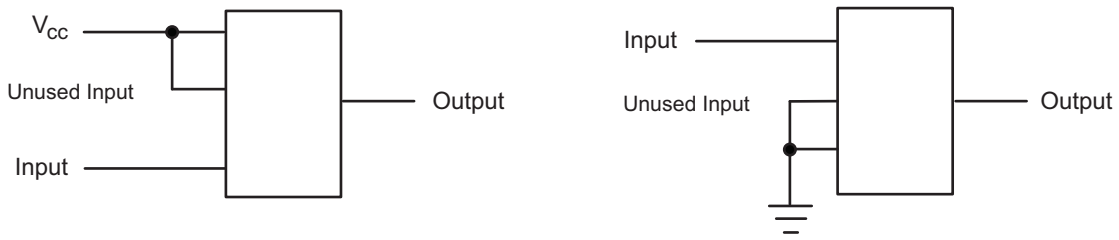



**Figure 6. Layout Diagram**


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# 13 Device and Documentation Support

## 13.1 Related Links

The table below lists quick access links. Categories include technical documents, support and community resources, tools and software, and quick access to sample or buy.

**Table 3. Related Links**

| PARTS | PRODUCT FOLDER | SAMPLE & BUY | TECHNICAL DOCUMENTS | TOOLS & SOFTWARE | SUPPORT & COMMUNITY |
|---|---|---|---|---|---|
| SN54LVC373A | Click here | Click here | Click here | Click here | Click here |
| SN74LVC373A | Click here | Click here | Click here | Click here | Click here |

## 13.2 Trademarks

All trademarks are the property of their respective owners.

## 13.3 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

## 13.4 Glossary

SLYZ022 — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

# 14 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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## PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|---|---|---|---|---|---|---|---|---|---|---|---|
| 5962-9757301Q2A | ACTIVE | LCCC | FK | 20 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-9757301Q2A SNJ54LVC 373AFK | Samples |
| 5962-9757301QRA | ACTIVE | CDIP | J | 20 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-9757301QR A SNJ54LVC373AJ | Samples |
| 5962-9757301QSA | ACTIVE | CFP | W | 20 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-9757301QS A SNJ54LVC373AW | Samples |
| SN74LVC373ADBR | ACTIVE | SSOP | DB | 20 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | LC373A | Samples |
| SN74LVC373ADGVR | ACTIVE | TVSOP | DGV | 20 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | LC373A | Samples |
| SN74LVC373ADW | ACTIVE | SOIC | DW | 20 | 25 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | LVC373A | Samples |
| SN74LVC373ADWG4 | ACTIVE | SOIC | DW | 20 | 25 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | LVC373A | Samples |
| SN74LVC373ADWR | ACTIVE | SOIC | DW | 20 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | LVC373A | Samples |
| SN74LVC373AN | ACTIVE | PDIP | N | 20 | 20 | RoHS & Green | NIPDAU | N / A for Pkg Type | -40 to 85 | SN74LVC373AN | Samples |
| SN74LVC373ANSR | ACTIVE | SO | NS | 20 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | LVC373A | Samples |
| SN74LVC373APW | ACTIVE | TSSOP | PW | 20 | 70 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | LC373A | Samples |
| SN74LVC373APWE4 | ACTIVE | TSSOP | PW | 20 | 70 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | LC373A | Samples |
| SN74LVC373APWG4 | ACTIVE | TSSOP | PW | 20 | 70 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | LC373A | Samples |
| SN74LVC373APWR | ACTIVE | TSSOP | PW | 20 | 2000 | RoHS & Green | NIPDAU \| SN | Level-1-260C-UNLIM | -40 to 85 | LC373A | Samples |
| SN74LVC373APWRG4 | ACTIVE | TSSOP | PW | 20 | 2000 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | LC373A | Samples |
| SN74LVC373APWT | ACTIVE | TSSOP | PW | 20 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | LC373A | Samples |
| SN74LVC373APWTE4 | ACTIVE | TSSOP | PW | 20 | 250 | RoHS & Green | NIPDAU | Level-1-260C-UNLIM | -40 to 85 | LC373A | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead finish/ Ball material (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|---|---|---|---|---|---|---|---|---|---|---|---|
| SN74LVC373ARGYR | ACTIVE | VQFN | RGY | 20 | 3000 | RoHS & Green | NIPDAU | Level-2-260C-1 YEAR | -40 to 85 | LC373A | Samples |
| SNJ54LVC373AFK | ACTIVE | LCCC | FK | 20 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-9757301Q2A SNJ54LVC 373AFK | Samples |
| SNJ54LVC373AJ | ACTIVE | CDIP | J | 20 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-9757301QR A SNJ54LVC373AJ | Samples |
| SNJ54LVC373AW | ACTIVE | CFP | W | 20 | 1 | Non-RoHS & Green | SNPB | N / A for Pkg Type | -55 to 125 | 5962-9757301QS A SNJ54LVC373AW | Samples |

(1) The marketing status values are defined as follows:
**ACTIVE:** Product device recommended for new designs.
**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.
**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

**OTHER QUALIFIED VERSIONS OF SN54LVC373A, SN74LVC373A :**

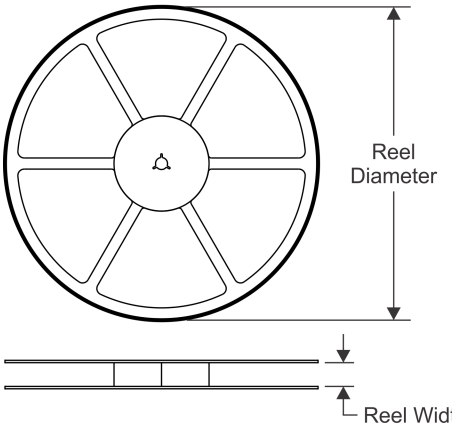
- Catalog: SN74LVC373A
- Enhanced Product: SN74LVC373A-EP, SN74LVC373A-EP
- Military: SN54LVC373A

NOTE: Qualified Version Definitions:

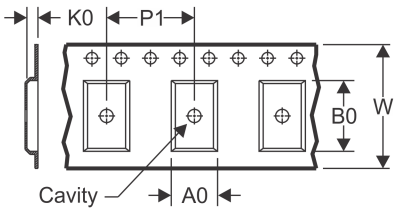
- Catalog - TI's standard catalog product
- Enhanced Product - Supports Defense, Aerospace and Medical Applications
- Military - QML certified for Military and Defense Applications

## TAPE AND REEL INFORMATION

REEL DIMENSIONS

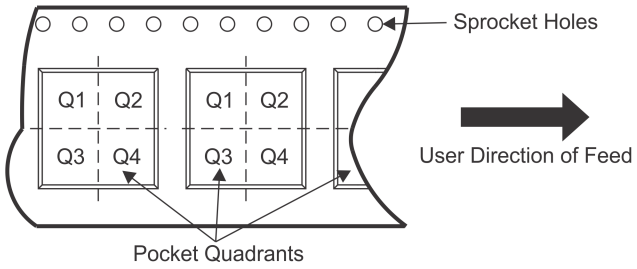



TAPE DIMENSIONS




| | |
|---|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

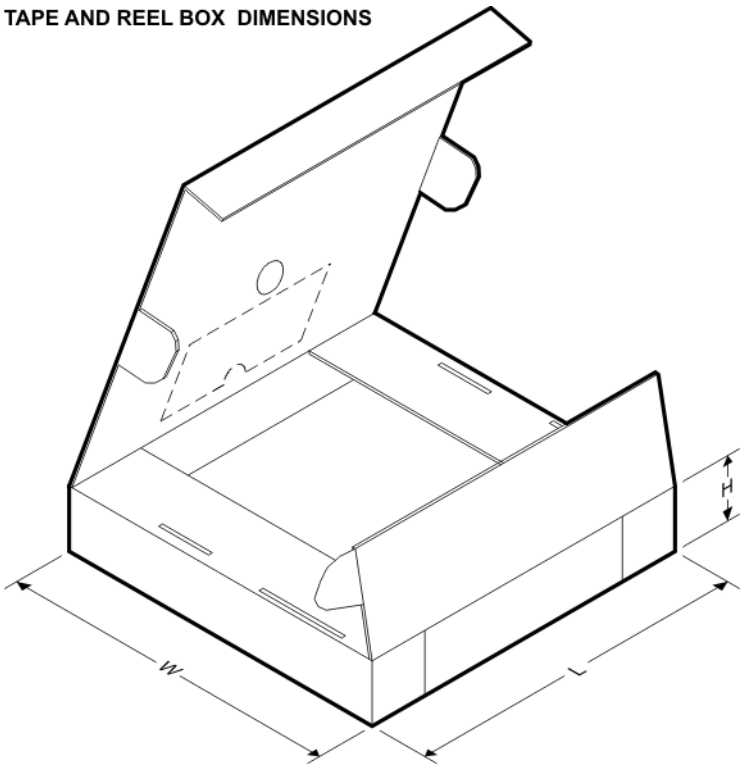
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE




*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|---|---|---|---|---|---|---|---|---|---|---|---|---|
| SN74LVC373ADBR | SSOP | DB | 20 | 2000 | 330.0 | 16.4 | 8.2 | 7.5 | 2.5 | 12.0 | 16.0 | Q1 |
| SN74LVC373ADGVR | TVSOP | DGV | 20 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| SN74LVC373ADWR | SOIC | DW | 20 | 2000 | 330.0 | 24.4 | 10.8 | 13.3 | 2.7 | 12.0 | 24.0 | Q1 |
| SN74LVC373ANSR | SO | NS | 20 | 2000 | 330.0 | 24.4 | 8.4 | 13.0 | 2.5 | 12.0 | 24.0 | Q1 |
| SN74LVC373APWR | TSSOP | PW | 20 | 2000 | 330.0 | 16.4 | 6.95 | 7.0 | 1.4 | 8.0 | 16.0 | Q1 |
| SN74LVC373APWR | TSSOP | PW | 20 | 2000 | 330.0 | 16.4 | 6.95 | 7.1 | 1.6 | 8.0 | 16.0 | Q1 |
| SN74LVC373APWRG4 | TSSOP | PW | 20 | 2000 | 330.0 | 16.4 | 6.95 | 7.0 | 1.4 | 8.0 | 16.0 | Q1 |
| SN74LVC373APWT | TSSOP | PW | 20 | 250 | 330.0 | 16.4 | 6.95 | 7.1 | 1.6 | 8.0 | 16.0 | Q1 |
| SN74LVC373ARGYR | VQFN | RGY | 20 | 3000 | 330.0 | 12.4 | 3.8 | 4.8 | 1.6 | 8.0 | 12.0 | Q1 |

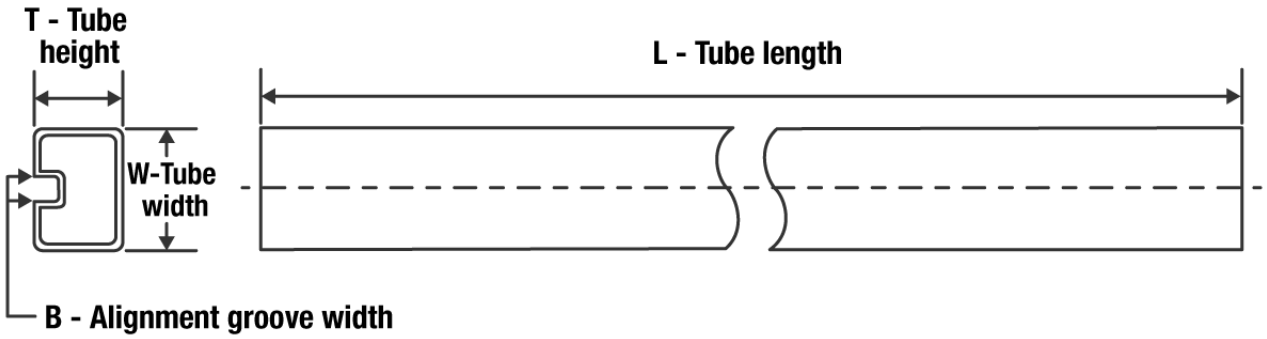
TAPE AND REEL BOX DIMENSIONS




*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|---|---|---|---|---|---|---|---|
| SN74LVC373ADBR | SSOP | DB | 20 | 2000 | 853.0 | 449.0 | 35.0 |
| SN74LVC373ADGVR | TVSOP | DGV | 20 | 2000 | 853.0 | 449.0 | 35.0 |
| SN74LVC373ADWR | SOIC | DW | 20 | 2000 | 367.0 | 367.0 | 45.0 |
| SN74LVC373ANSR | SO | NS | 20 | 2000 | 367.0 | 367.0 | 45.0 |
| SN74LVC373APWR | TSSOP | PW | 20 | 2000 | 853.0 | 449.0 | 35.0 |
| SN74LVC373APWR | TSSOP | PW | 20 | 2000 | 364.0 | 364.0 | 27.0 |
| SN74LVC373APWRG4 | TSSOP | PW | 20 | 2000 | 853.0 | 449.0 | 35.0 |
| SN74LVC373APWT | TSSOP | PW | 20 | 250 | 853.0 | 449.0 | 35.0 |
| SN74LVC373ARGYR | VQFN | RGY | 20 | 3000 | 853.0 | 449.0 | 35.0 |

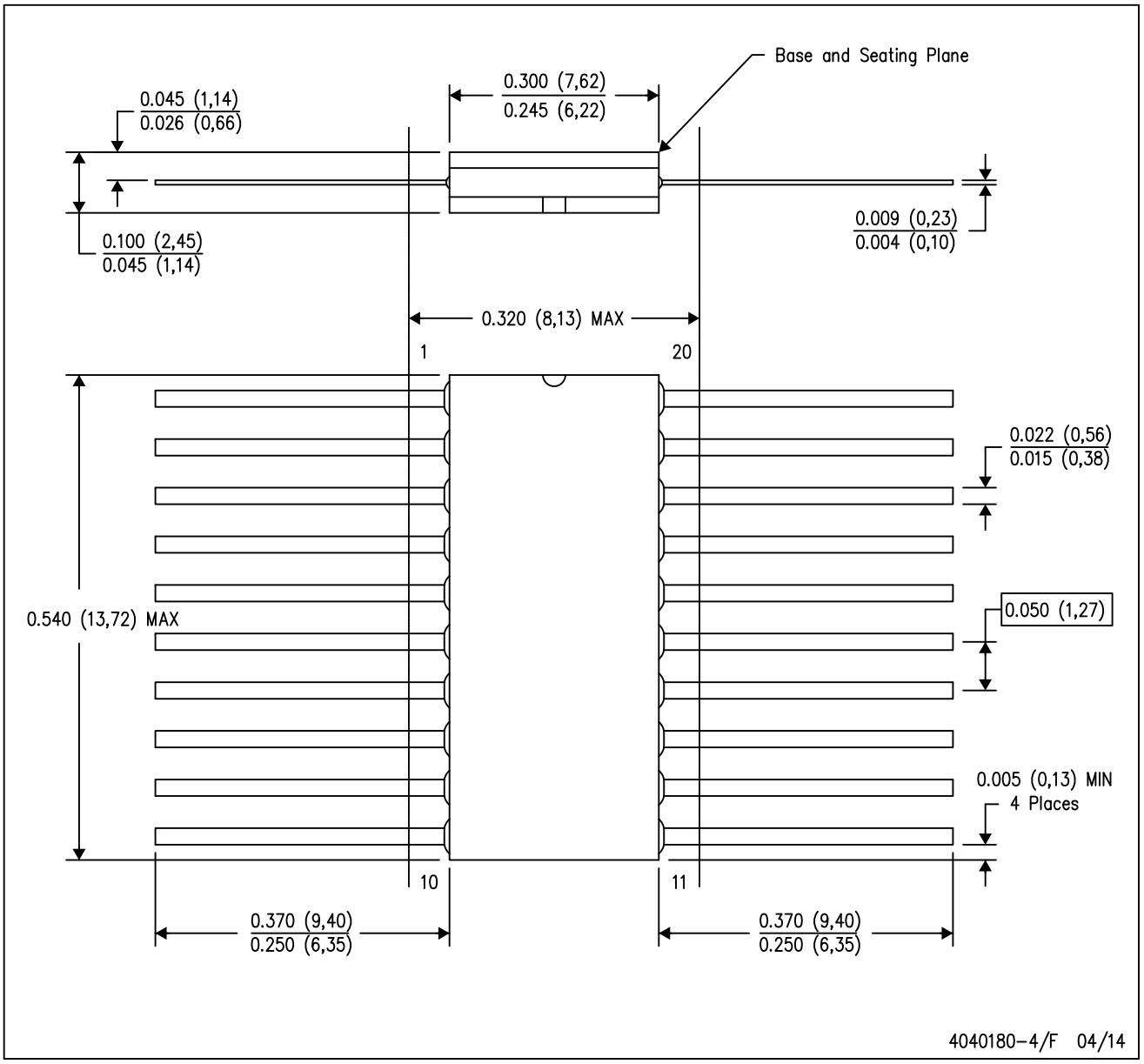
## TUBE




*All dimensions are nominal

| Device | Package Name | Package Type | Pins | SPQ | L (mm) | W (mm) | T (µm) | B (mm) |
|---|---|---|---|---|---|---|---|---|
| 5962-9757301Q2A | FK | LCCC | 20 | 1 | 506.98 | 12.06 | 2030 | NA |
| SN74LVC373ADW | DW | SOIC | 20 | 25 | 507 | 12.83 | 5080 | 6.6 |
| SN74LVC373ADWG4 | DW | SOIC | 20 | 25 | 507 | 12.83 | 5080 | 6.6 |
| SN74LVC373AN | N | PDIP | 20 | 20 | 506 | 13.97 | 11230 | 4.32 |
| SN74LVC373APW | PW | TSSOP | 20 | 70 | 530 | 10.2 | 3600 | 3.5 |
| SN74LVC373APWE4 | PW | TSSOP | 20 | 70 | 530 | 10.2 | 3600 | 3.5 |
| SN74LVC373APWG4 | PW | TSSOP | 20 | 70 | 530 | 10.2 | 3600 | 3.5 |
| SNJ54LVC373AFK | FK | LCCC | 20 | 1 | 506.98 | 12.06 | 2030 | NA |

W (R–GDFP–F20) CERAMIC DUAL FLATPACK



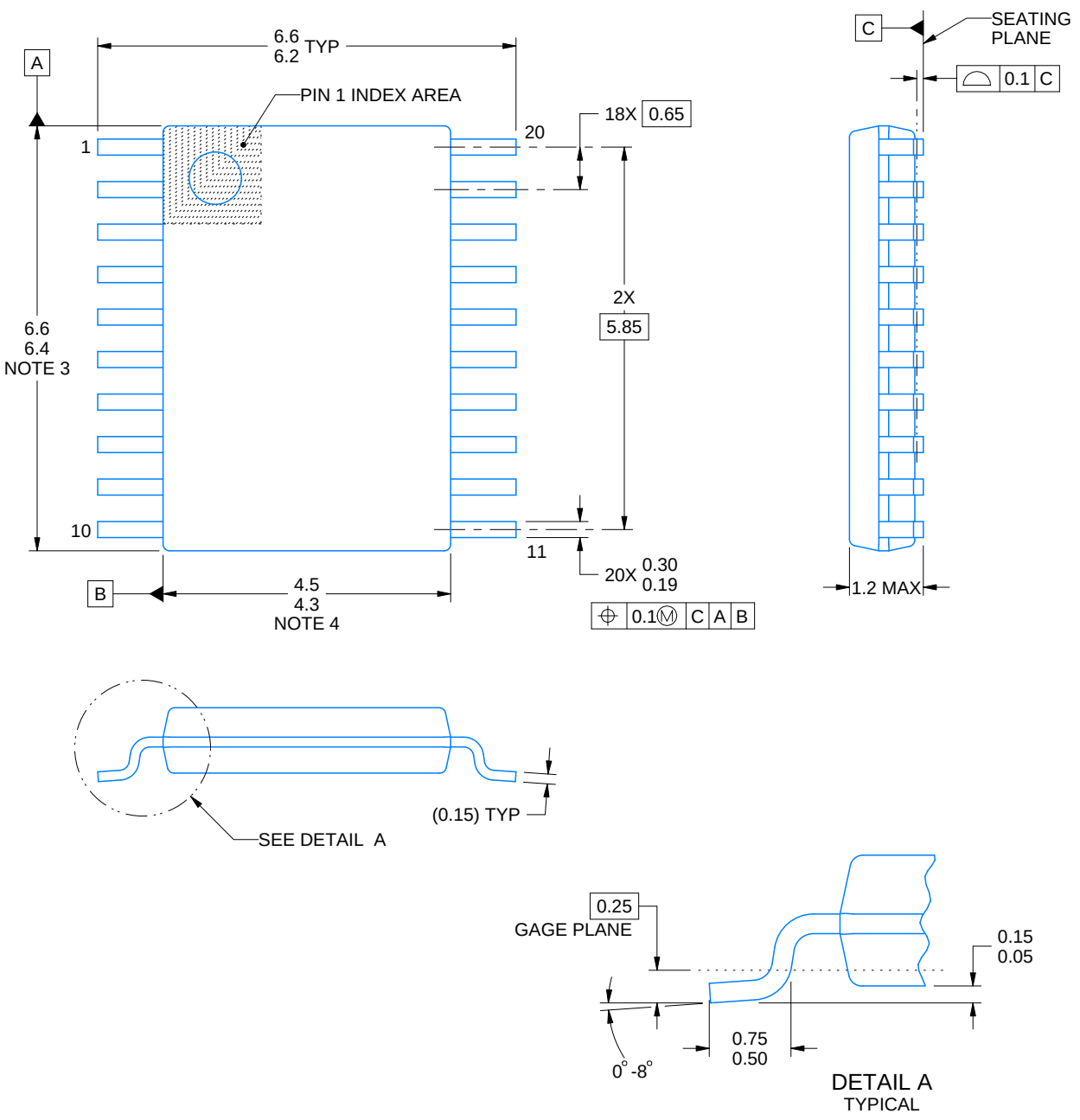

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within Mil–Std 1835 GDFP2–F20

# PACKAGE OUTLINE

## PW0020A

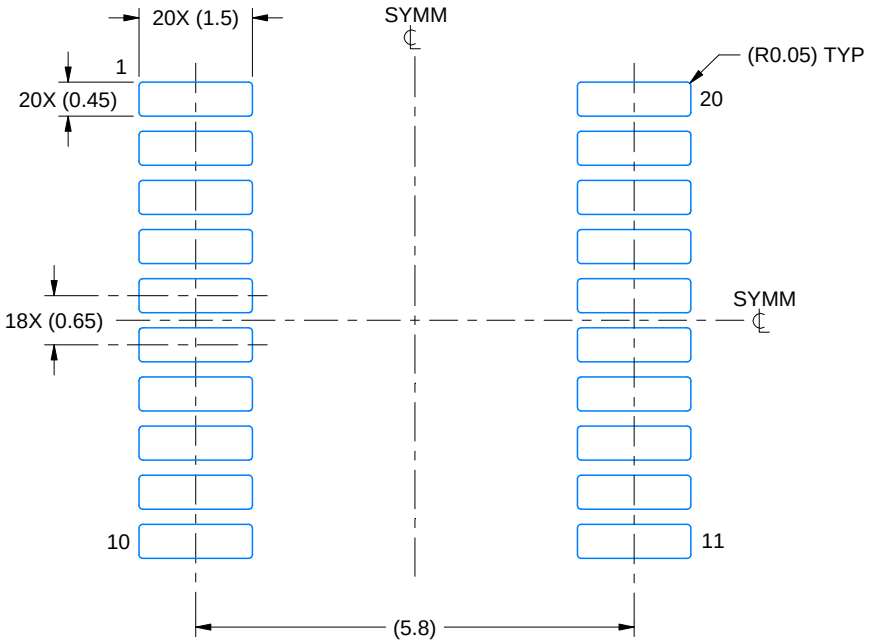
## TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE




NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.




LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X

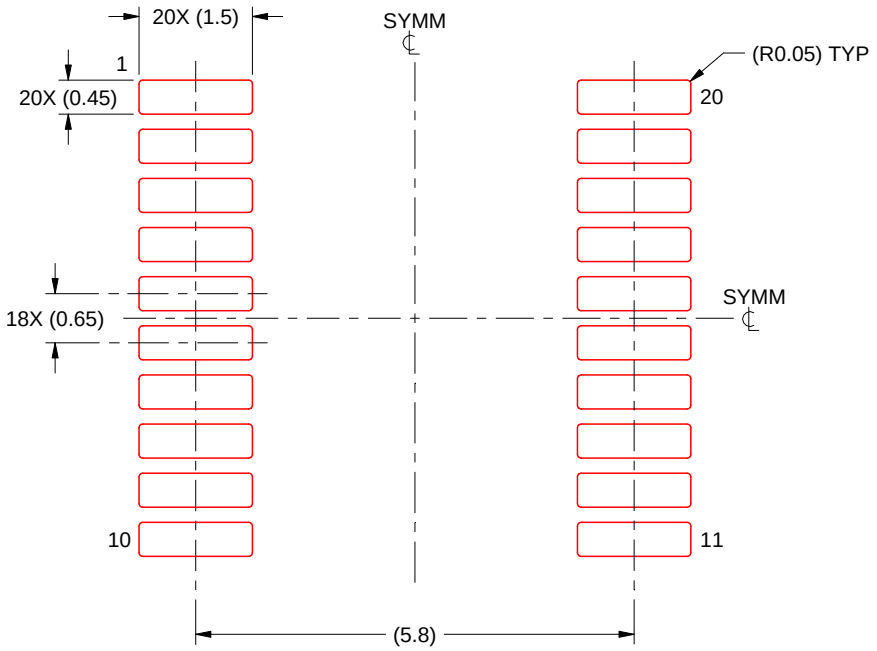



SOLDER MASK DETAILS

4220206/A 02/2017

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



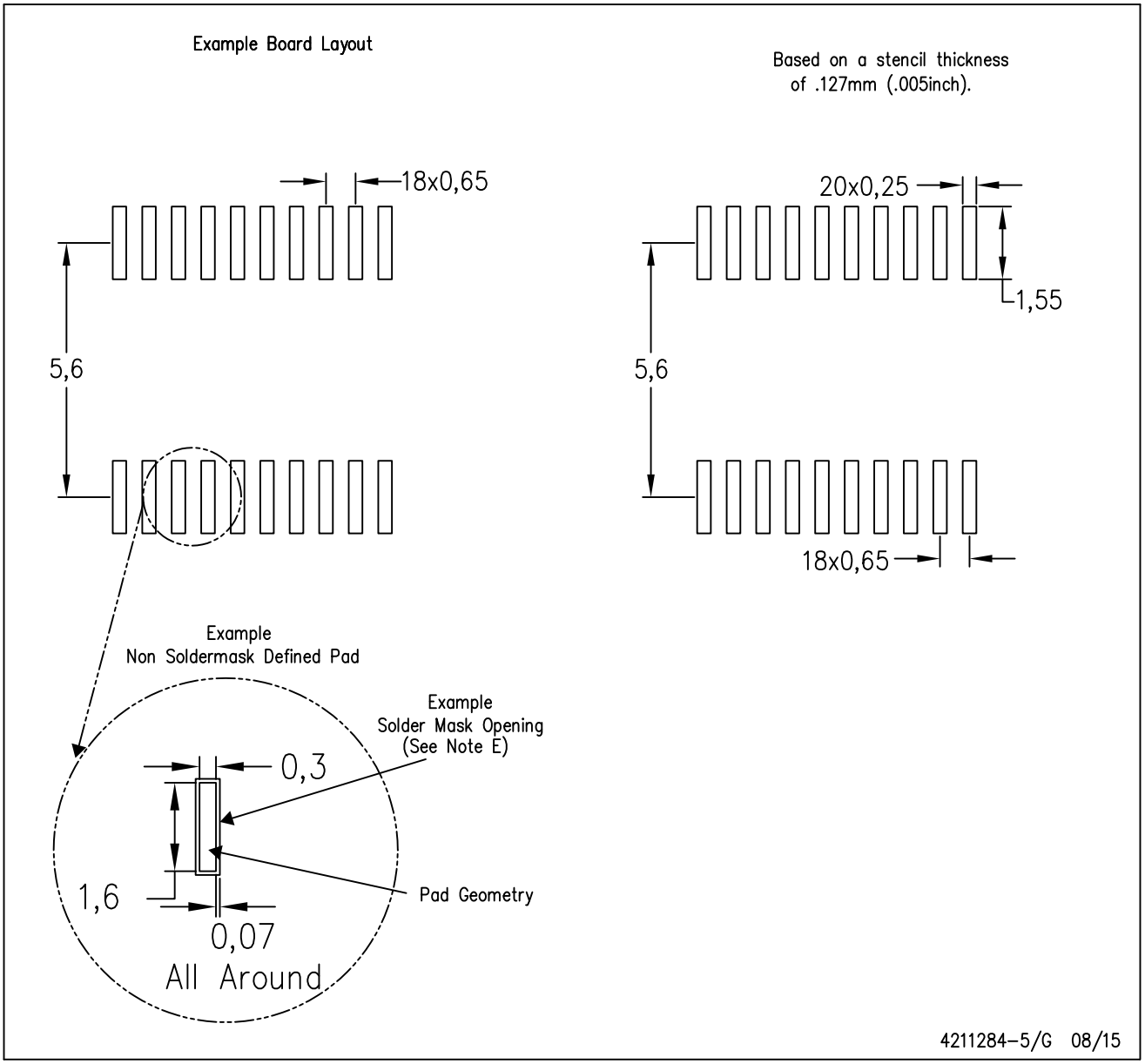

SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4220206/A 02/2017

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

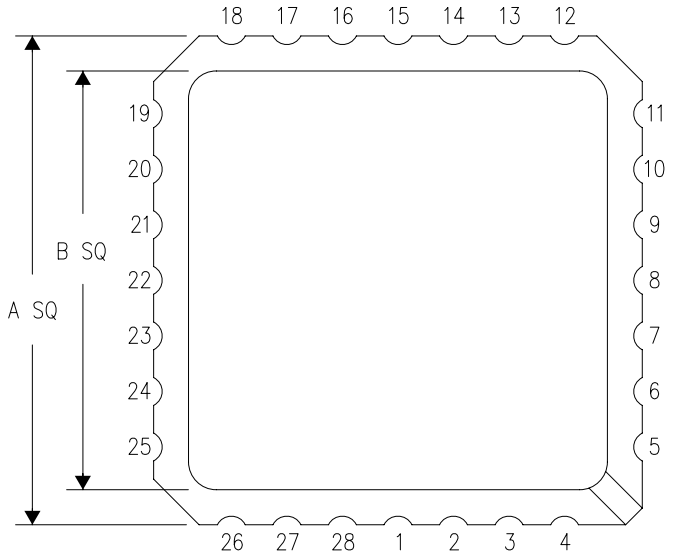
PW (R–PDSO–G20) PLASTIC SMALL OUTLINE



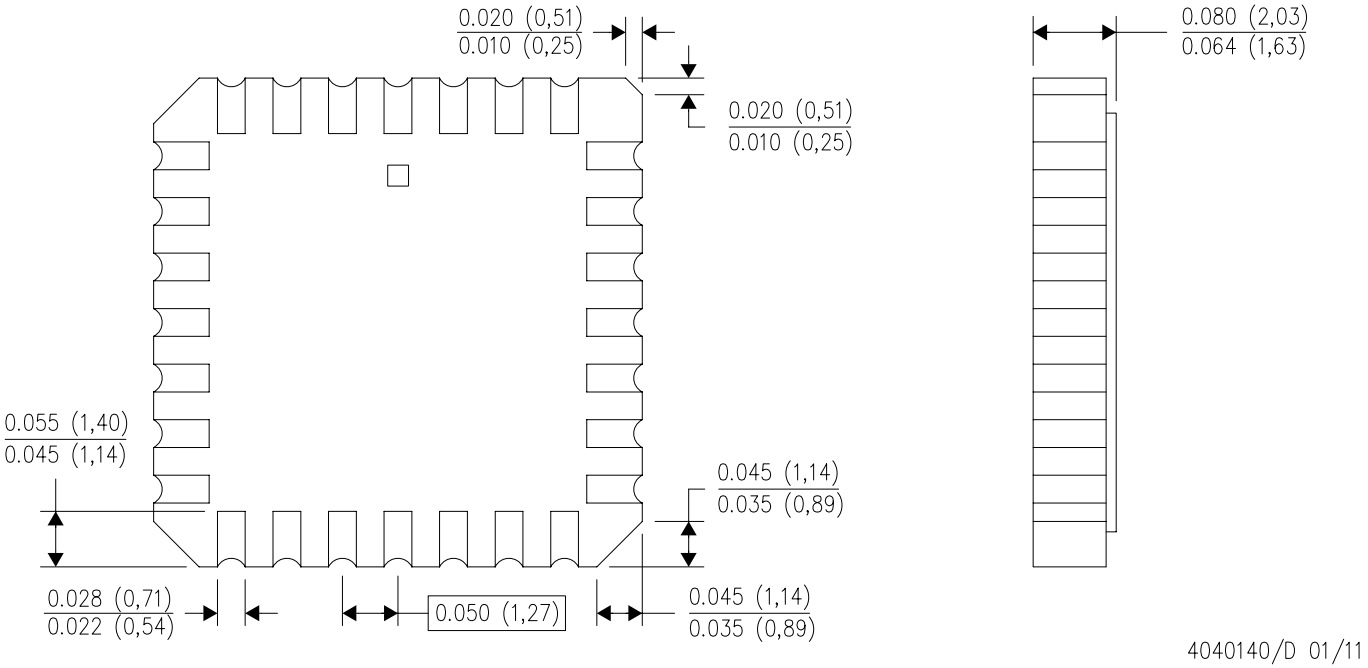

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate design.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

FK (S–CQCC–N**) LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN




| NO. OF TERMINALS ** | A | | B | |
|---|---|---|---|---|
| | MIN | MAX | MIN | MAX |
| 20 | 0.342 (8,69) | 0.358 (9,09) | 0.307 (7,80) | 0.358 (9,09) |
| 28 | 0.442 (11,23) | 0.458 (11,63) | 0.406 (10,31) | 0.458 (11,63) |
| 44 | 0.640 (16,26) | 0.660 (16,76) | 0.495 (12,58) | 0.560 (14,22) |
| 52 | 0.740 (18,78) | 0.761 (19,32) | 0.495 (12,58) | 0.560 (14,22) |
| 68 | 0.938 (23,83) | 0.962 (24,43) | 0.850 (21,6) | 0.858 (21,8) |
| 84 | 1.141 (28,99) | 1.165 (29,59) | 1.047 (26,6) | 1.063 (27,0) |




4040140/D 01/11

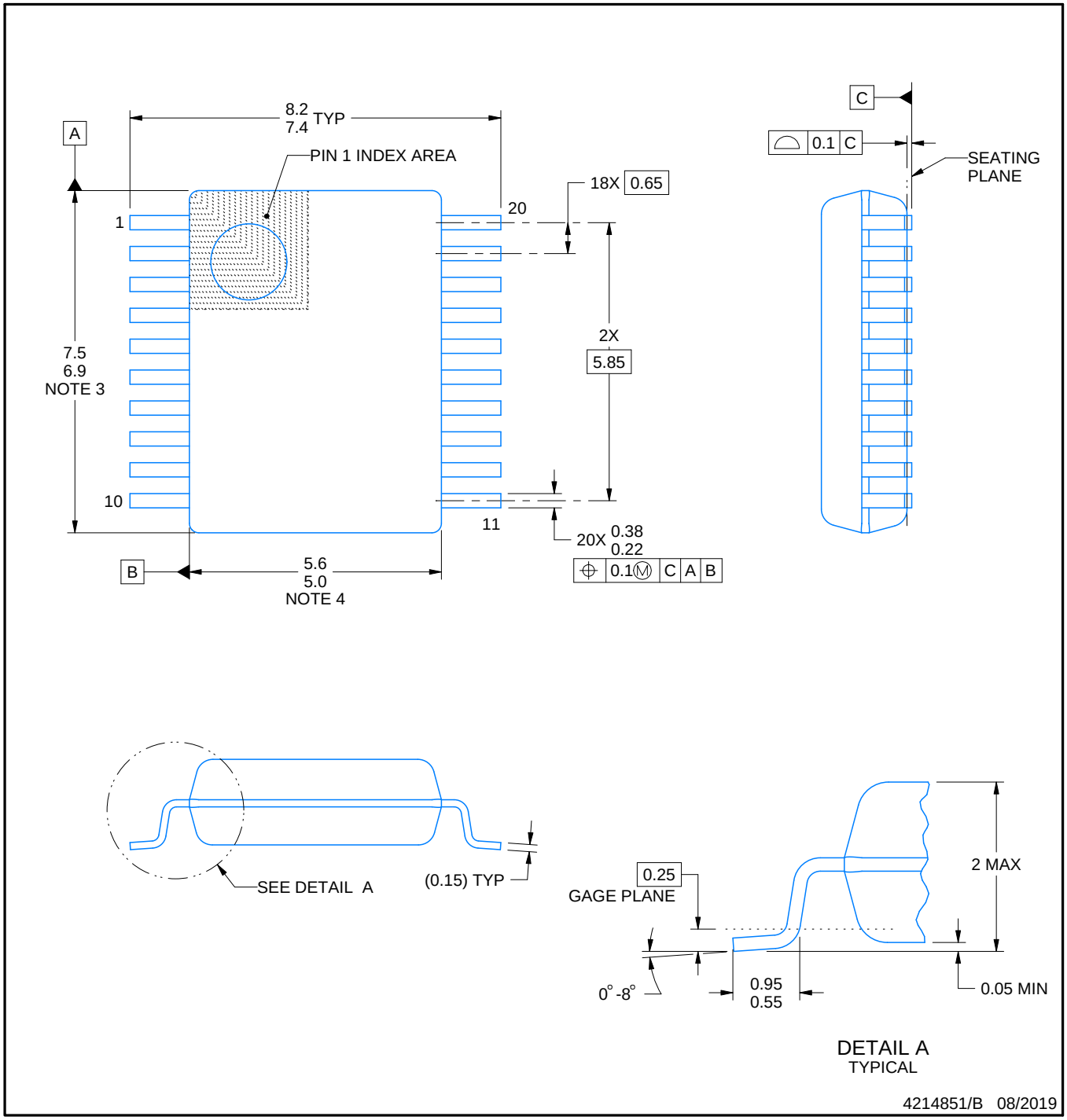
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. Falls within JEDEC MS–004

# PACKAGE OUTLINE

## DB0020A

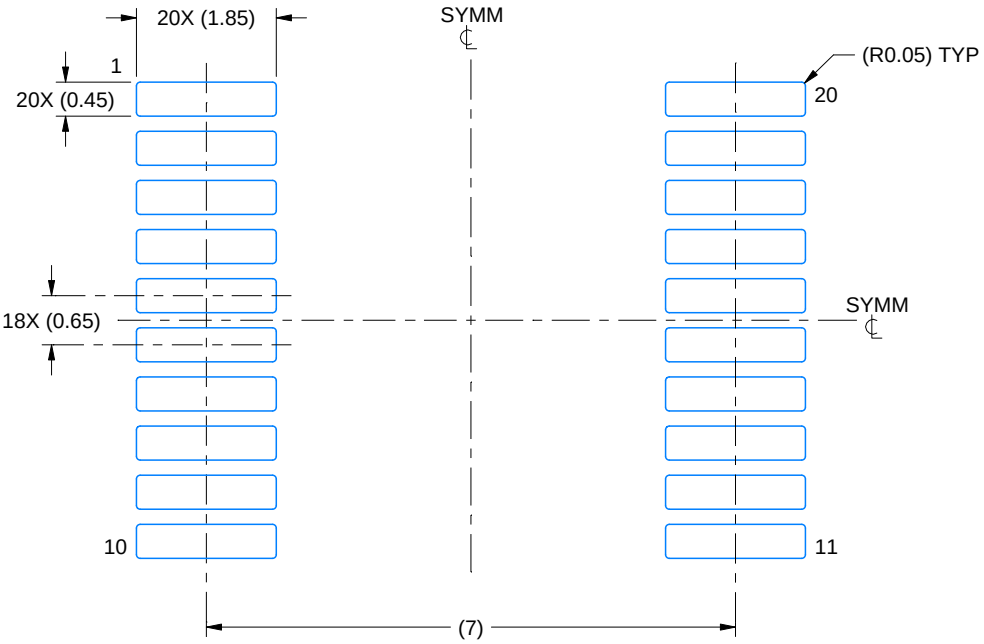
## SSOP - 2 mm max height

SMALL OUTLINE PACKAGE

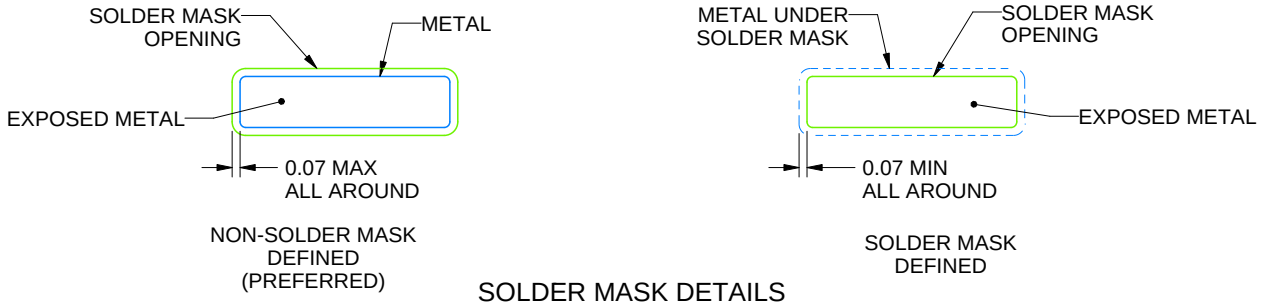



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-150.




LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X




SOLDER MASK DETAILS

4214851/B 08/2019

NOTES: (continued)

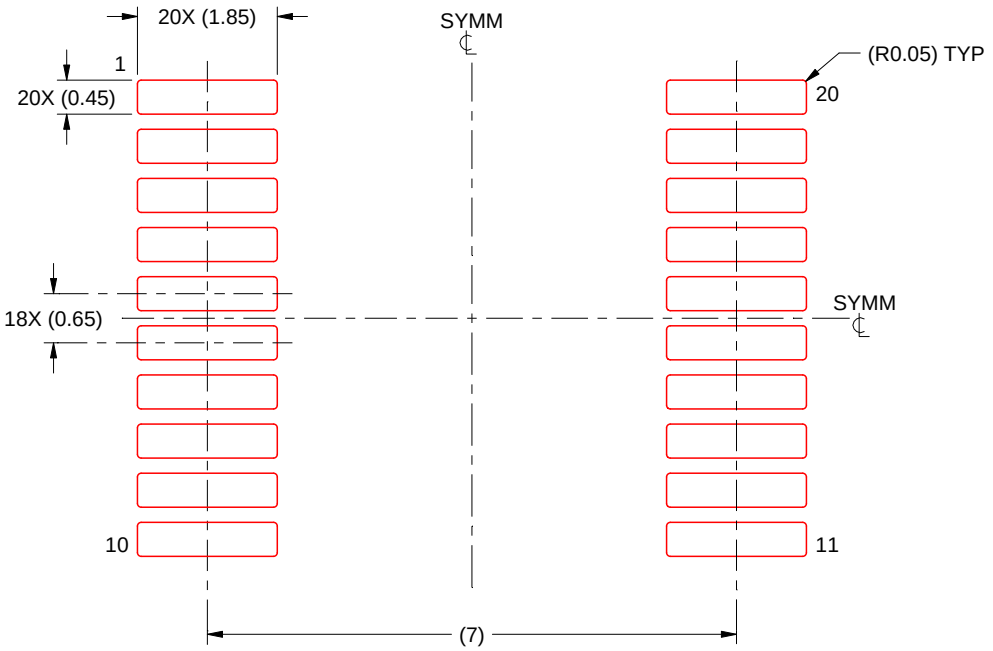
6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

# EXAMPLE STENCIL DESIGN

## DB0020A

## SSOP - 2 mm max height

SMALL OUTLINE PACKAGE




SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

4214851/B 08/2019

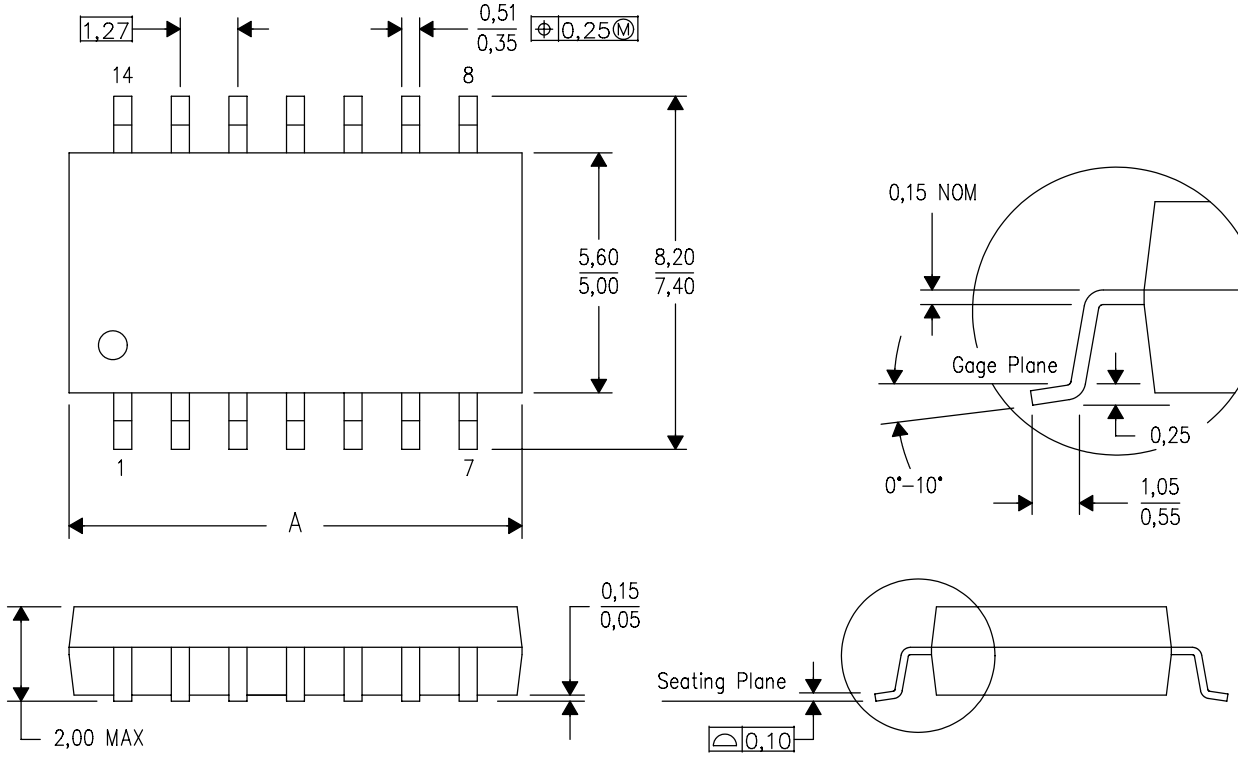
NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

## MECHANICAL DATA

**NS (R-PDSO-G**)** **PLASTIC SMALL-OUTLINE PACKAGE**

**14-PINS SHOWN**




| DIM \ PINS ** | 14 | 16 | 20 | 24 |
|---|---|---|---|---|
| A MAX | 10,50 | 10,50 | 12,90 | 15,30 |
| A MIN | 9,90 | 9,90 | 12,30 | 14,70 |

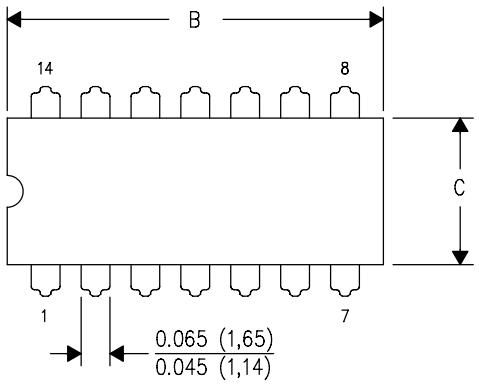
4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

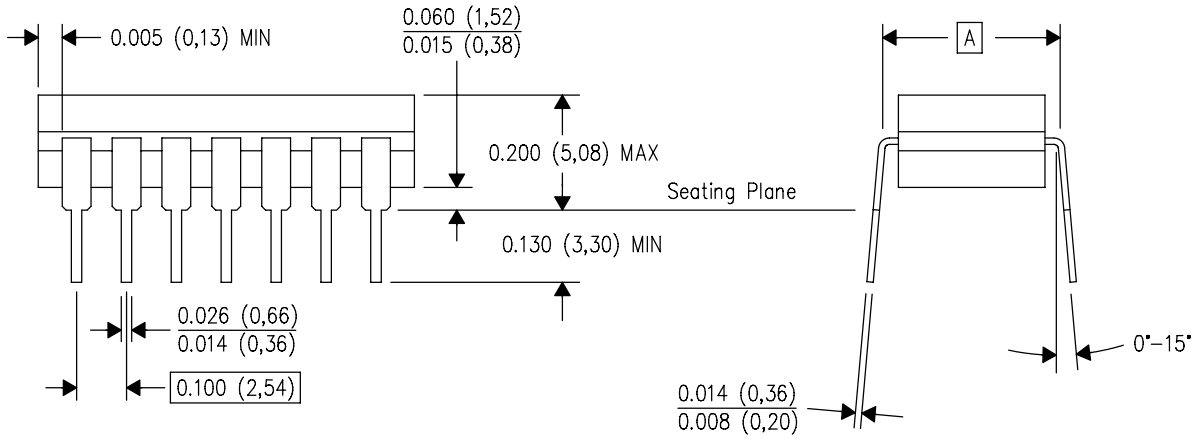
J (R–GDIP–T**)

14 LEADS SHOWN

# CERAMIC DUAL IN–LINE PACKAGE




| DIM \ PINS ** | 14 | 16 | 18 | 20 |
|---|---|---|---|---|
| A | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC |
| B MAX | 0.785 (19,94) | .840 (21,34) | 0.960 (24,38) | 1.060 (26,92) |
| B MIN | — | — | — | — |
| C MAX | 0.300 (7,62) | 0.300 (7,62) | 0.310 (7,87) | 0.300 (7,62) |
| C MIN | 0.245 (6,22) | 0.245 (6,22) | 0.220 (5,59) | 0.245 (6,22) |

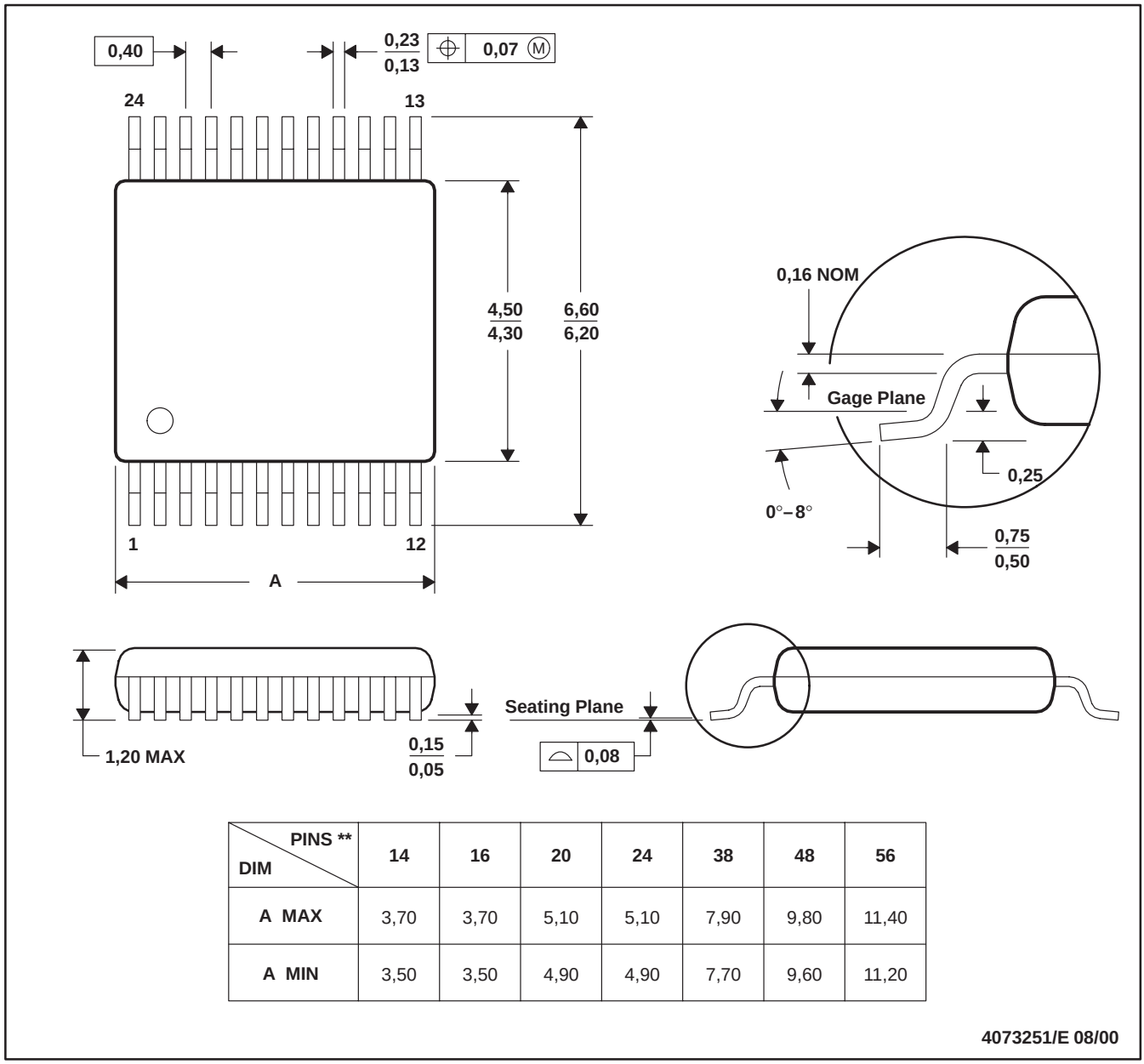



4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

**DGV (R-PDSO-G**)** **PLASTIC SMALL-OUTLINE**

**24 PINS SHOWN**




| DIM \ PINS ** | 14 | 16 | 20 | 24 | 38 | 48 | 56 |
|---|---|---|---|---|---|---|---|
| A MAX | 3,70 | 3,70 | 5,10 | 5,10 | 7,90 | 9,80 | 11,40 |
| A MIN | 3,50 | 3,50 | 4,90 | 4,90 | 7,70 | 9,60 | 11,20 |

**4073251/E 08/00**

NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
D. Falls within JEDEC: 24/48 Pins – MO-153
14/16/20/56 Pins – MO-194

# GENERIC PACKAGE VIEW

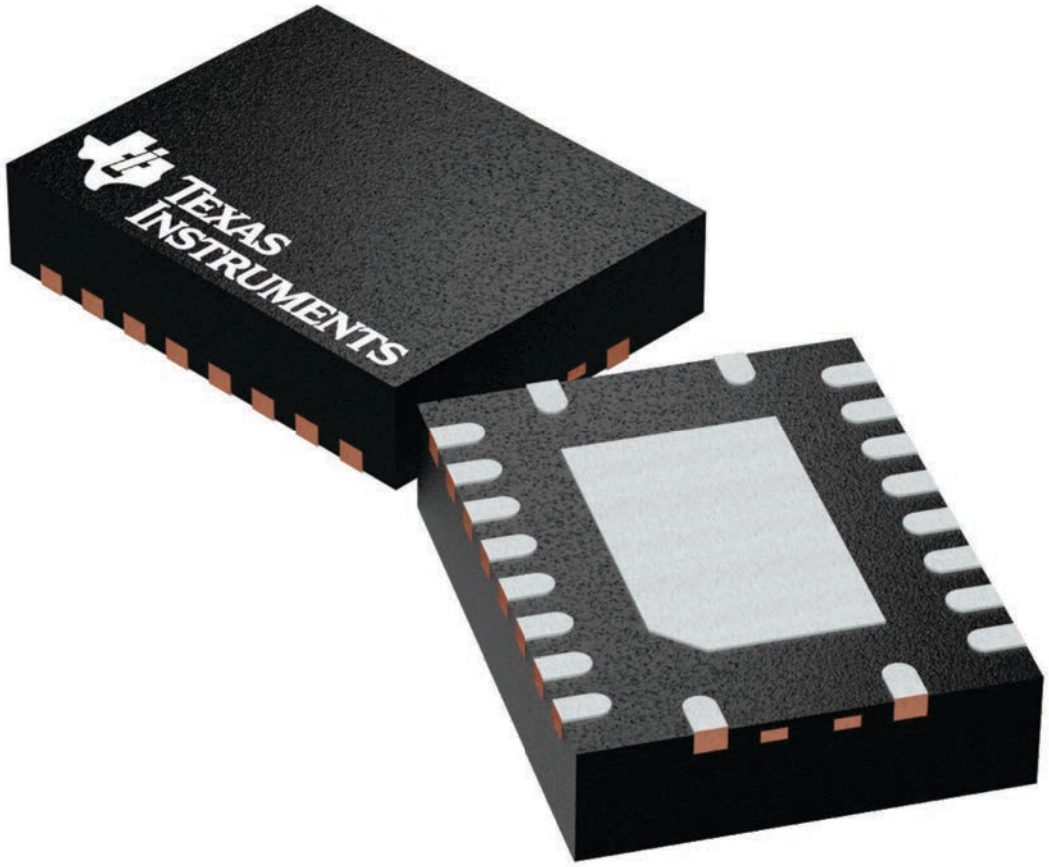
## RGY 20

## VQFN - 1 mm max height

**3.5 x 4.5, 0.5 mm pitch**

PLASTIC QUAD FGLATPACK - NO LEAD

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



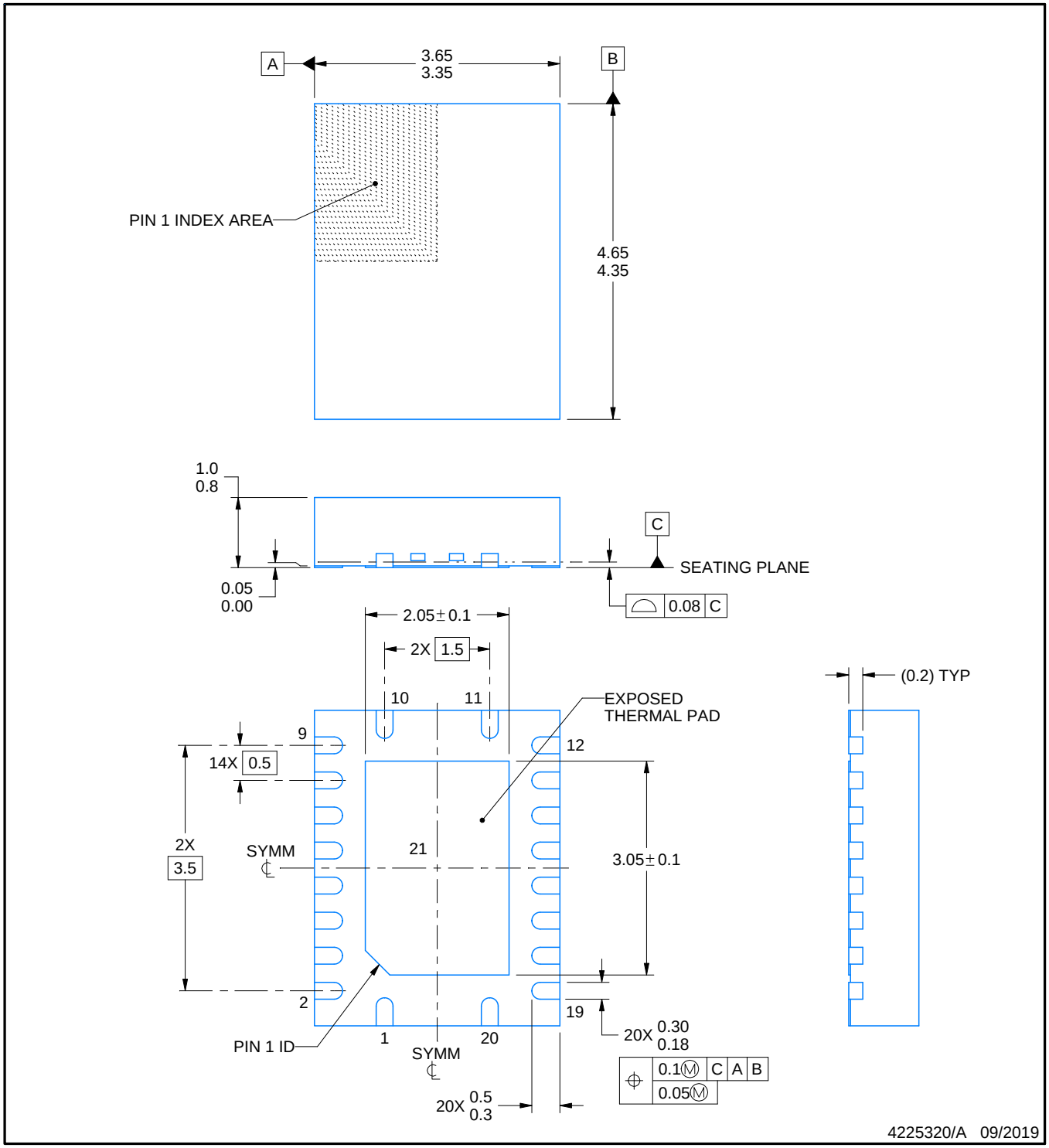

4225264/A

# PACKAGE OUTLINE

## RGY0020A

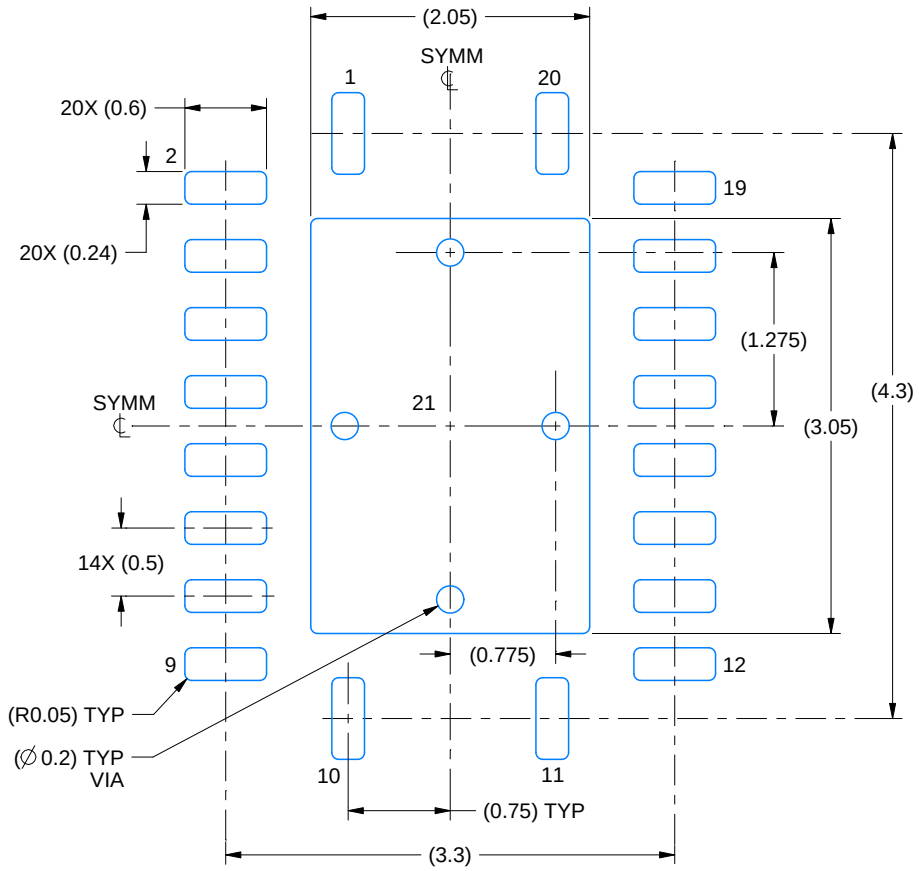
## VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD

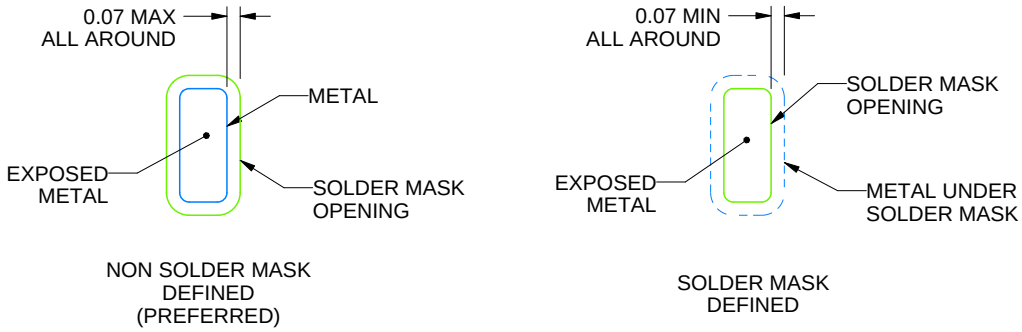



NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.




LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:18X

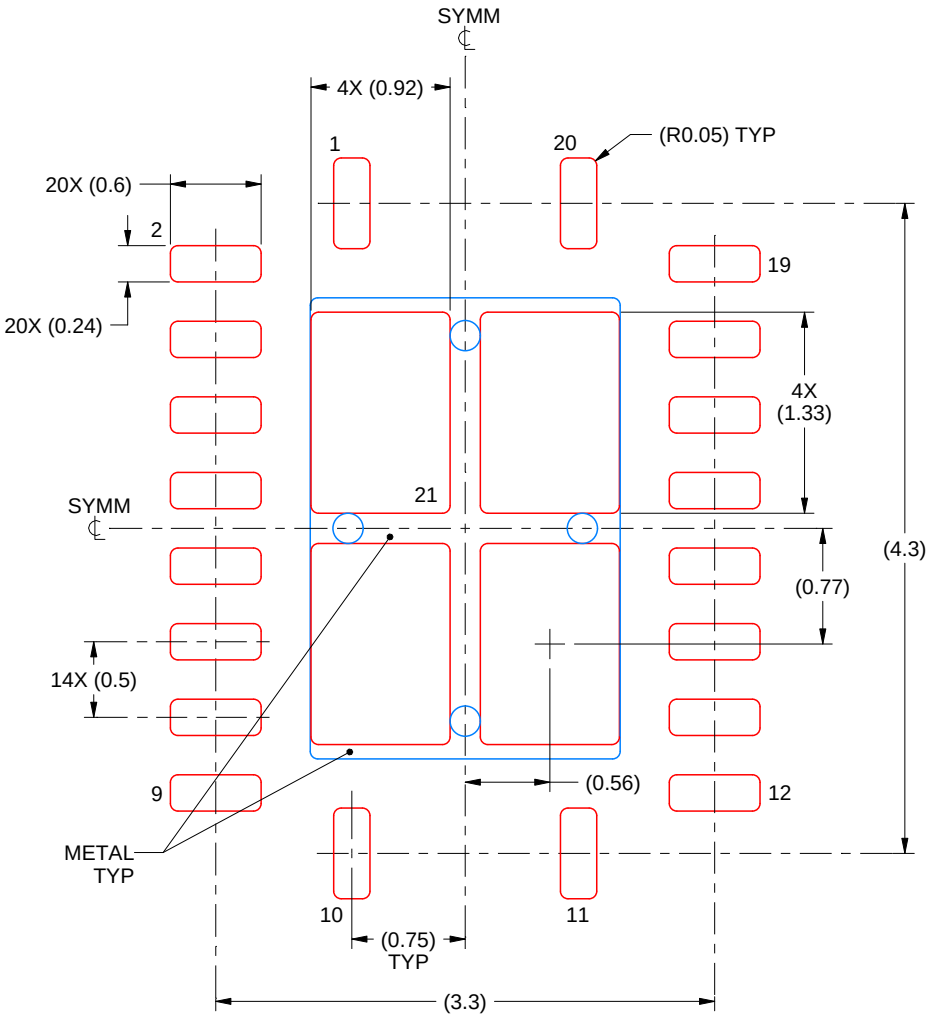



SOLDER MASK DETAILS

4225320/A 09/2019

NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.




SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 21
78% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE
SCALE:20X

4225320/A 09/2019

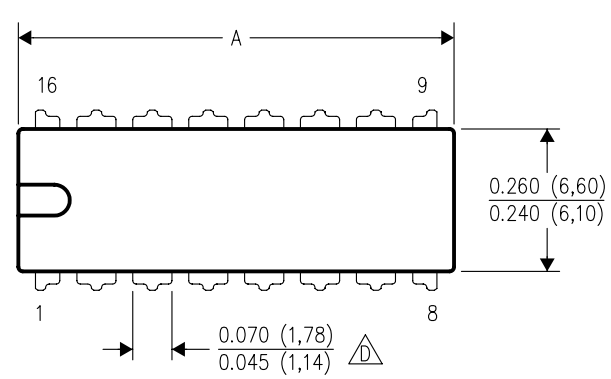
NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

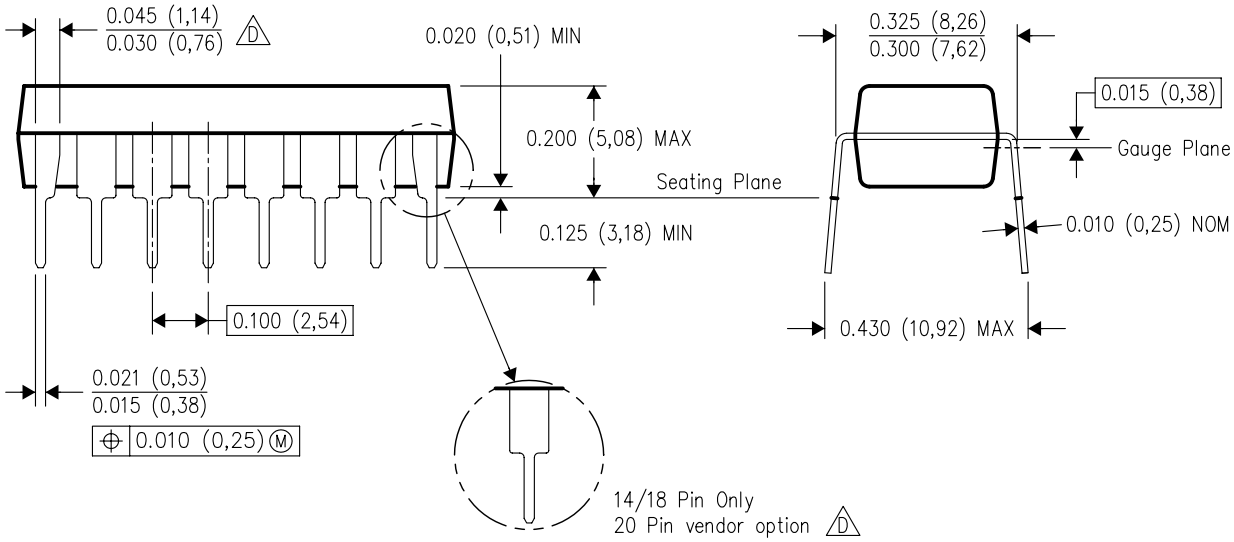
## N (R–PDIP–T**)

## PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN

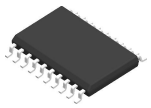



| DIM \ PINS ** | 14 | 16 | 18 | 20 |
|---|---|---|---|---|
| A MAX | 0.775 (19,69) | 0.775 (19,69) | 0.920 (23,37) | 1.060 (26,92) |
| A MIN | 0.745 (18,92) | 0.745 (18,92) | 0.850 (21,59) | 0.940 (23,88) |
| MS–001 VARIATION (C) | AA | BB | AC | AD |




4040049/E 12/2002

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

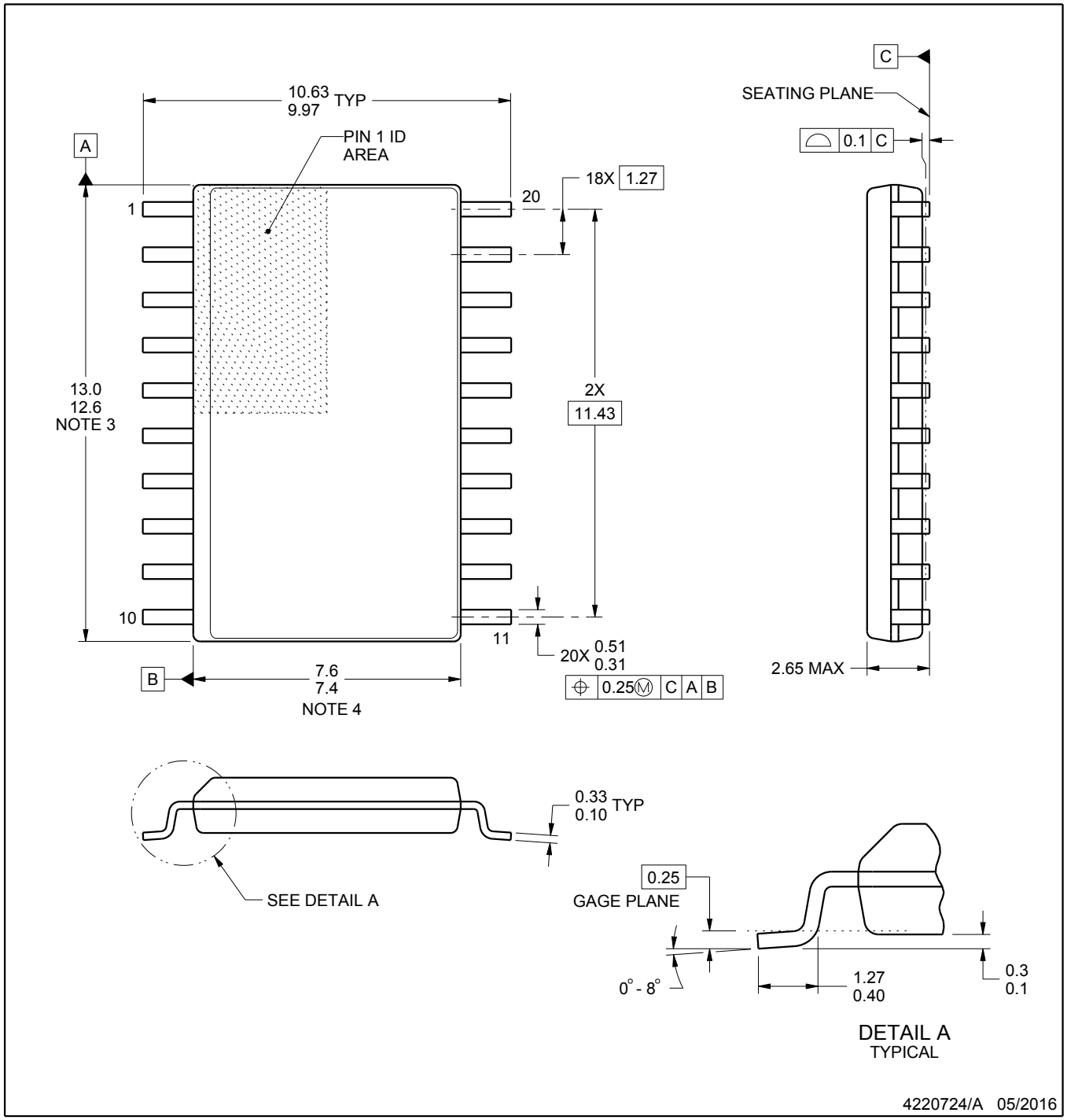


# PACKAGE OUTLINE

## DW0020A

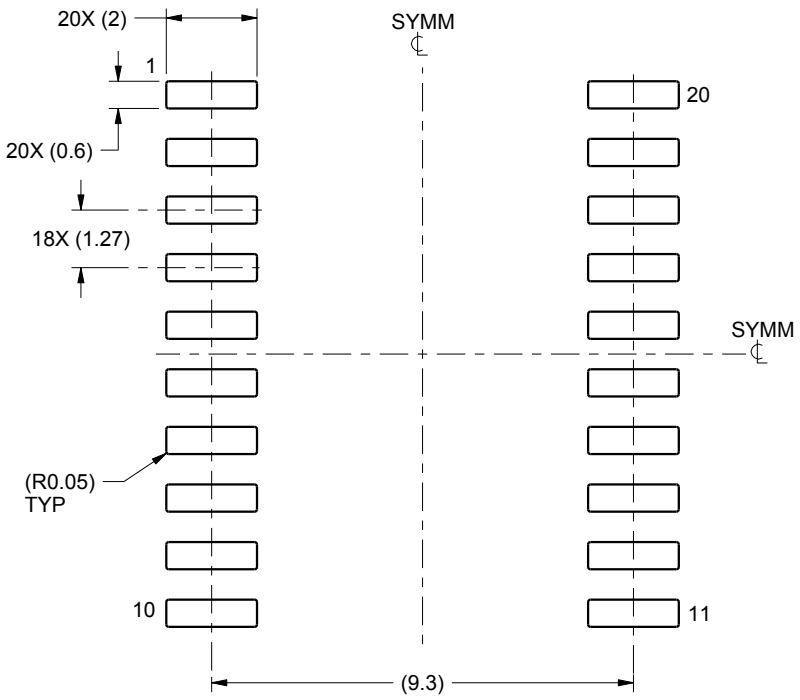
## SOIC - 2.65 mm max height

SOIC

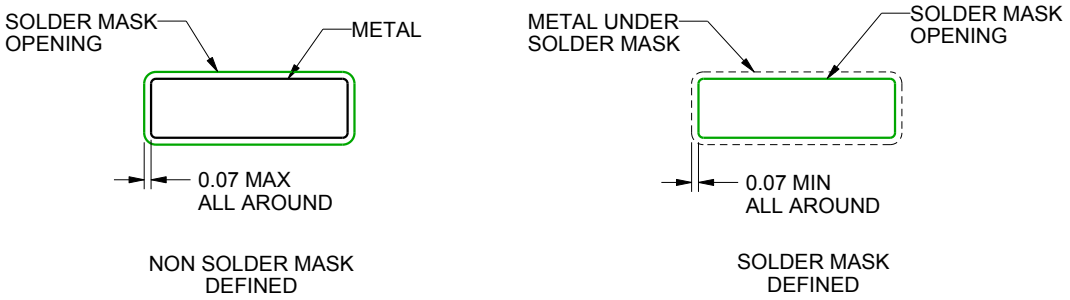



NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.




LAND PATTERN EXAMPLE
SCALE:6X

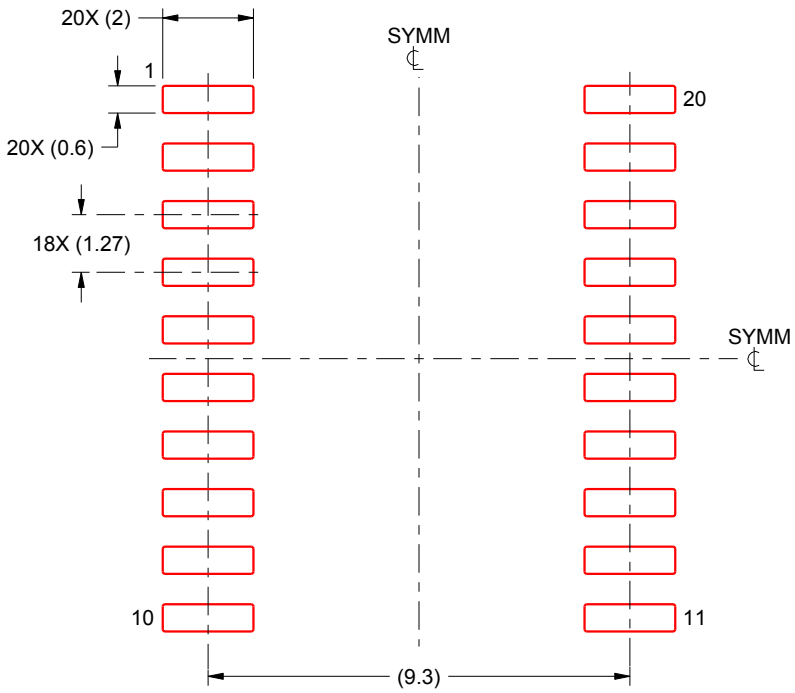



SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.




SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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